

MultiConnect® mDot™

MTDOT Developer Guide

MultiConnect mDot Developer Guide

Models: MTDOT-915-xxx, MTDOT-868-xxx includes also the MTUDK2-ST-MDOT Developer Kit

Part Number: S000612, Version 1.4

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Contents

Chapter 1 Product Overview	6
Overview	6
Getting Started.....	6
Documentation Overview	7
Related Documentation	7
mbed Documentation	7
Programming the mDot Microcontroller	7
General mBed Links	8
mDot Platform	8
EUI and Networking	8
Product Build Options.....	9
Chapter 2 Mechanical Drawings with Pinouts	10
MTDOT-xxx-X1P-SMA.....	10
MTDOT-xxx-X1P-U.FL.....	11
MTDOT-xxx-X1-SMA.....	12
MTDOT-xxx-X1-UFL	13
MTDOT-xxx-M1-UFL.....	14
MTDOT-xxx-M1-TRC.....	15
Chapter 3 Specifications and Pin Information	16
MTDOT Specifications	16
Power Draw.....	19
Electrical Characteristics	20
Pin Information	20
mDot Pinout Design Notes.....	22
Serial Pinout Notes.....	22
Serial Settings.....	22
LoRa	22
Throughput Rates.....	22
Range	23
Chapter 4 Antennas	24
Antenna System	24
Pulse Electronics Antenna.....	24
Antenna Specifications	24
OEM Integration	24
FCC & IC Information to Consumers	24
FCC Grant Notes.....	25
Host Labeling.....	25

Chapter 5 Safety Information	26
Handling Precautions	26
Radio Frequency (RF) Safety	26
Sécurité relative aux appareils à radiofréquence (RF).....	26
Interference with Pacemakers and Other Medical Devices	27
Potential interference	27
Precautions for pacemaker wearers	27
Device Maintenance	27
User Responsibility.....	27
Chapter 6 Regulatory Information	28
EMC, Safety, and R&TTE Directive Compliance	28
47 CFR Part 15 Regulation Class B Devices	28
FCC Interference Notice	28
FCC Grant	29
FCC Part 15.....	29
FCC Notice	29
Industry Canada Class B Notice.....	29
Industry Canada	30
Chapter 7 Environmental Notices	31
Waste Electrical and Electronic Equipment Statement	31
WEEE Directive.....	31
Instructions for Disposal of WEEE by Users in the European Union	31
REACH Statement	32
Registration of Substances.....	32
Substances of Very High Concern (SVHC)	32
Restriction of the Use of Hazardous Substances (RoHS)	33
Information on HS/TS Substances According to Chinese Standards	34
Information on HS/TS Substances According to Chinese Standards (in Chinese)	35
Chapter 8 Labels	36
Approvals and Certification.....	36
Example Labels.....	36
Chapter 9 Developer Kit Overview	37
Developer Board Overview	37
Developer Board Features	37
MTUDK2-ST-MDOT Developer Kit Contents	37
MTUDK2-ST-CELL Developer Kit Contents	37
Chapter 10 Board Components	39
Developer Board	39
Developer Board Connectors.....	41
Board Components	41

LED Indicators	42
Chapter 11 Developer Board Installation	43
Installing an mDot on the Developer Board	43
Arduino Shield	44
mDot Arduino Pins	44
Installing an Arduino Shield with an mDot	44
RSMA to U.FL Cables	45
Connecting an Antenna through the Developer Board Connectors	45
Chapter 12 Developer Board Schematics.....	46
Block Diagram	46
Schematics	47
Chapter 13 Design Considerations.....	52
Noise Suppression Design	52
PC Board Layout Guideline	52
User Accessible Areas	52
Electromagnetic Interference	53
Electrostatic Discharge Control.....	53
USB Design	54
Chapter 14 AT Commands.....	55
MultiTech AT Command Set	55
General Commands.....	55
Network/Addressing Commands	55
Radio Configuration	56
Send/Receive	57
Sleep/Serial Data Mode Options.....	57
Index.....	59

Chapter 1 Product Overview

Overview

The MultiConnect mDot is a programmable, long-range RF module that provides encrypted data connectivity to sensors, industrial equipment, and remote appliances. By using LoRa™ Long Range Spread Spectrum technology, bi-directional data communication can be maintained for distances up to 5 miles/8 km line of sight, deep into buildings, or within noisy environments* using the unlicensed ISM bands in North America, Europe and worldwide. mDot simplifies local connectivity for Internet of Things (IoT) applications.

The mDot features an integrated ARM® Cortex®-M4 processor and mbed™ compatible software library for developers to control, monitor and bring edge intelligence to their Internet of Things (IoT) applications.

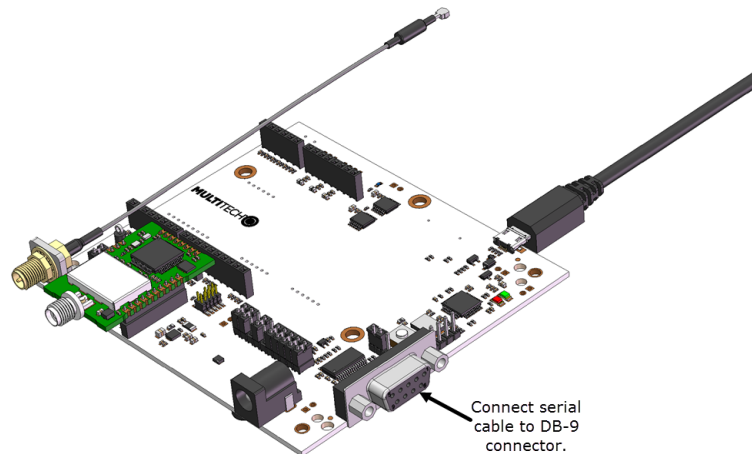
*Actual distance depends on conditions, configuration, antennas, desired throughput, and usage frequency. In dense urban environments, a typical range is 1-2 miles.

Getting Started

Getting started depends on what you want to do. By default, mDot ships with firmware that supports AT Commands that use the serial I/O. Refer to *Chapter 14, AT Commands*.

To send commands to the mDot:

1. Mount the mDot on the developer board. For details, refer to *Chapter 11, Developer Board Installation*.
2. Connect a serial cable into the DB-9 connector.



3. Open communications software, such as HyperTerminal or TeraTerm.
4. Set the following:
 - Baud rate = 115,200
 - Data bits = 8
 - Parity = N
 - Stop bits = 1
 - Flow control = Off

Two serial interfaces are available through the USB interface, one is used to program the mDot and the other is for debug messages. Refer to “mDot Pinout Design Notes” in *Chapter 3, Specifications and Pin Information* for information on which pins are available out of the box.

To develop using mbed, the mDot mbed page includes libraries and test cases. Refer to “mBed Documentation” for details and links.

For help setting up a MultiConnect® Conduit™ to send data to and from an mDot, refer to “Related Documentation.”

Documentation Overview

This manual is one part of mDot documentation. Refer to the *Related Documentation* and *mbed* sections for additional information needed to program your mDot and integrate your application with the MultiConnect Conduit gateway.

This document includes the following sections:

- **mDot device information:** Mechanical drawings, specifications, safety and regulatory information, and other device specific content. Chapters 1-8
- **Universal Developer Kit information:** Using the MTUDK-ST-MDOT Developer Kit, including design considerations, schematics, and installation and operation information. Chapters 9-13
- **AT commands:** Includes MultiTech AT Commands. Chapter 14.

This manual is available at www.multitech.com/support.

Related Documentation

Application notes, LoRa information, and documentation for related products such as the MultiConnect Conduit (MTCDT) gateway and the LoRa accessory card (MTAC-LORA) are available on the MultiTech developer site. This site includes information on using the Conduit with mDots. Go to: www.multitech.net

mbed Documentation

ARM mbed is a free, open-source platform and operating system for embedded devices using the ARM Cortex-M microcontrollers. The mbed website provides free software libraries, hardware designs, and online tools for rapid prototyping of products. The platform includes a standards-based C/C++ SDK, a microcontroller HDK, and supported development boards, an online compiler and online developer collaboration tools.

Note: To send and receive data, you need a LoRaWAN 1.0 gateway, such as MultiTech's MultiConnect Conduit (MTCDT) with an MTAC-LORA accessory card installed.

Programming the mDot Microcontroller

With the mDot and the MTUDK2-ST-xx developer board, use the ARM mbed ecosystem to program the microcontroller. Compile in the cloud or locally, copy the resulting binary file to the mbed USB drive, and reset the mDot.

Note: To program the mDot, you need an mDot model with programming header, model MTDOT-xx-X1P-SMA.

On the mDot mbed page, MultiTech supplies source code for non-RF portions of the mDot and MTAC-LORA cards. To comply with FCC and ETSI certification, some portions of the software will be available only as binary libraries.

General mBed Links

- Explore mbed: <http://developer.mbed.org/explore>
- Getting Started with mbed: <http://developer.mbed.org/getting-started>
- mbed Handbook: <http://developer.mbed.org/handbook/Homepage>

mDot Platform

The mDot mbed page includes the mDot library, firmware, and test cases
<https://developer.mbed.org/platforms/MTS-mDot-F411>

EUI and Networking

All mDots have a factory-programmed Extended Unique Identifier (EUI). This is marked as **Node** on the mDot label.

To connect an mDot to a network, you will need to program it with the network ID for the network you are connecting to as well as the network key and application key. For information on setting up mDots as part of a LoRa network, go to: www.multitech.net

Product Build Options

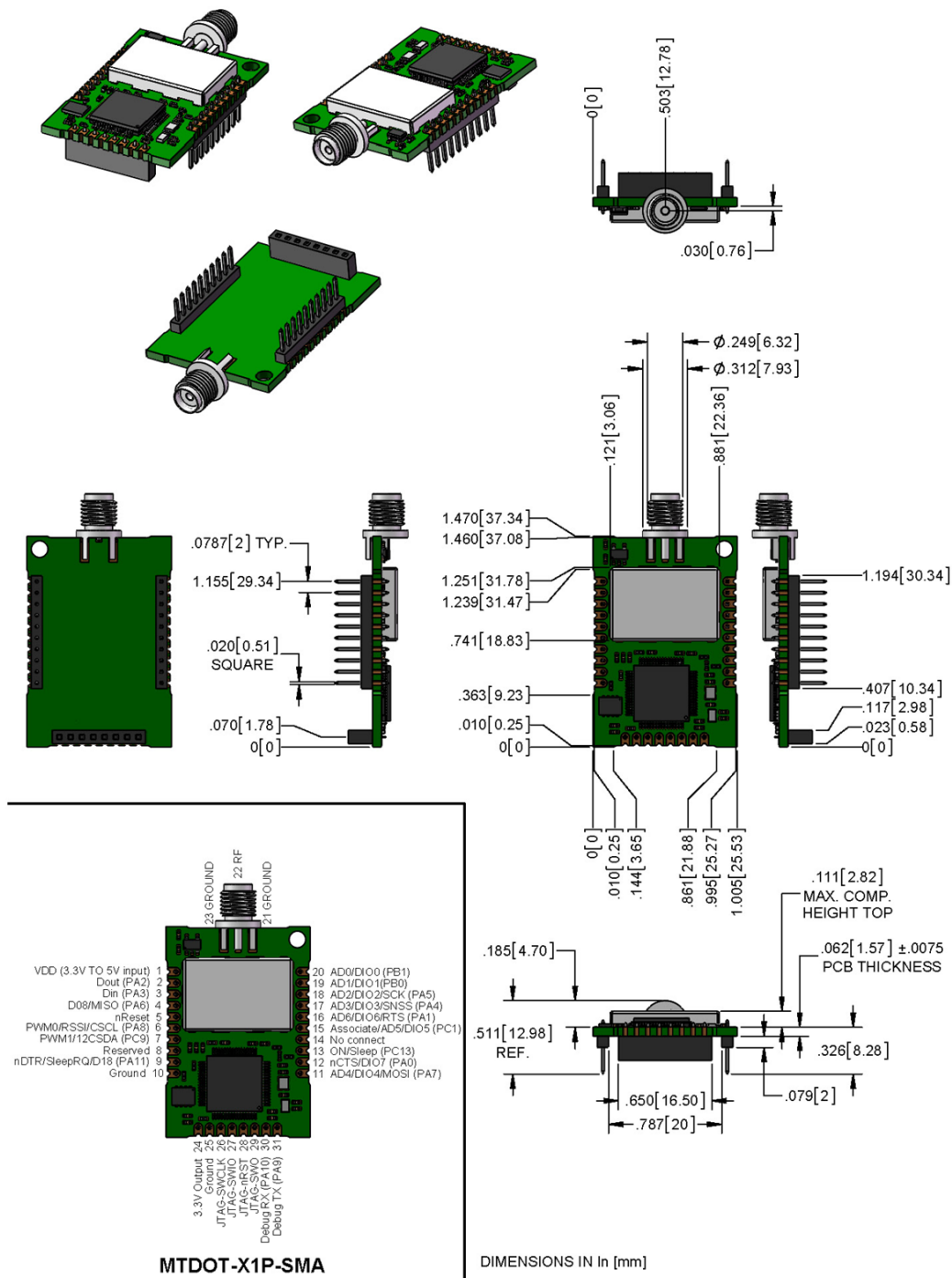
Product	Description	Quantity to Order
North America		
MTDOT-915-X1-SMA	915 MHz XBee LoRa SMA	1 or 50
MTDOT-915-X1P-SMA	915 MHz XBee LoRa SMA with Programming Header	1
MTDOT-915-X1-UFL	915 MHz XBee LoRa U.FL	1 or 50
MTDOT-915-M1-UFL	915 MHz SMT LoRa U.FL	1 or 100
MTDOT-915-M1-TRC	915 MHz SMT LoRa RF Pad	1 or 100
EMEA		
MTDOT-868-X1-SMA	868 MHz XBee LoRa SMA	1 or 50
MTDOT-868-X1P-SMA	868 MHz XBee LoRa SMA with Programming Header	1
MTDOT-868-X1-UFL	868 MHz XBee LoRa U.FL	1 or 50
MTDOT-868-M1-UFL	868 MHz SMT LoRa U.FL	1 or 100
MTDOT-868-M1-TRC	868 MHz SMT LoRa RF Pad	1 or 100
Developer Kits		
MTUDK2-ST-MDOT	mDot Developer Kit	1

Note:

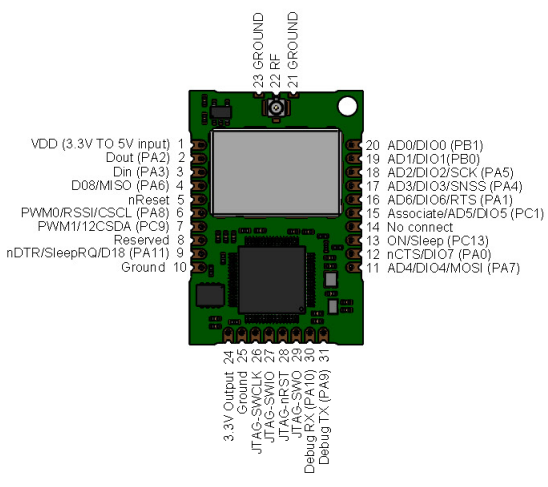
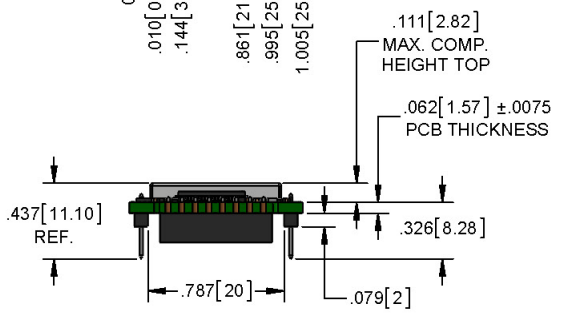
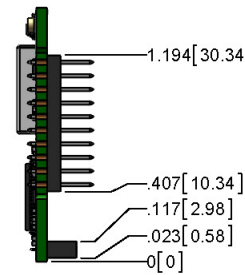
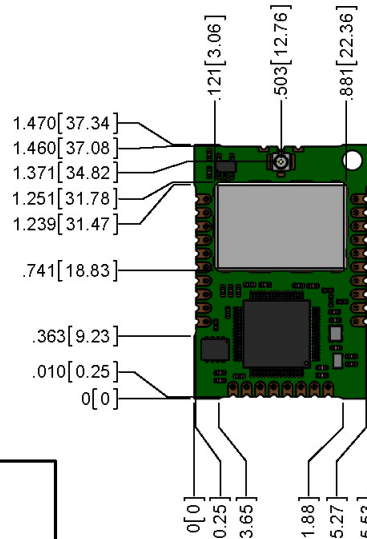
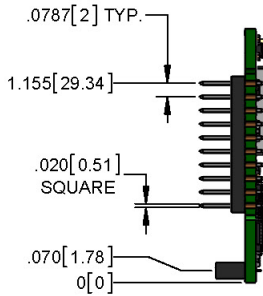
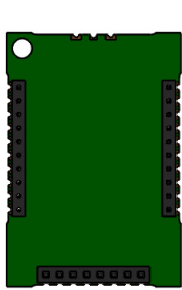
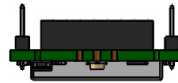
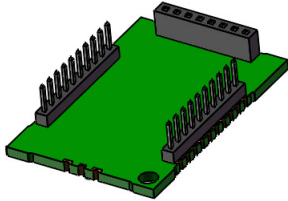
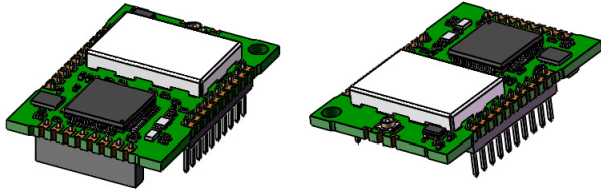
- The complete product code may end in .Rx. For example, MTDOT-915-M1-X1.Rx, where R is revision and x is the revision number.

Chapter 2 Mechanical Drawings with Pinouts

MTDOT-xxx-X1P-SMA



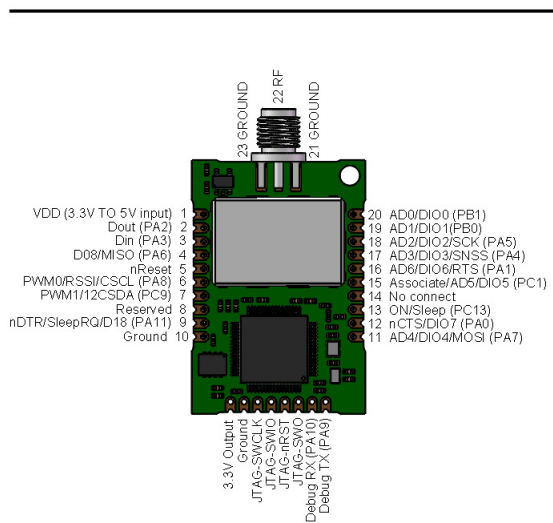
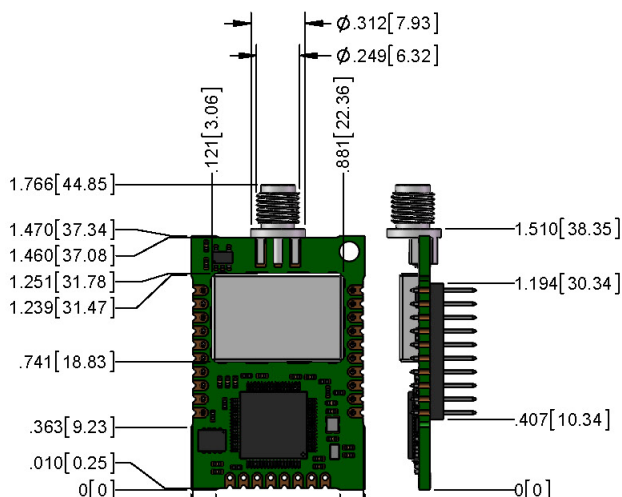
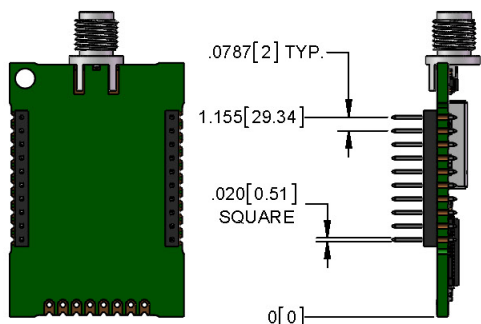
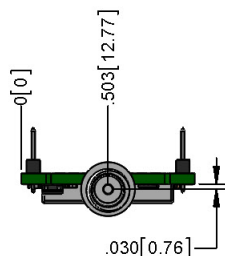
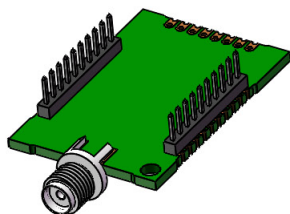
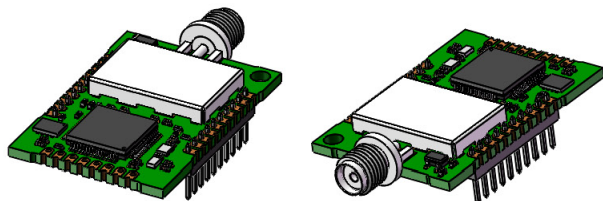
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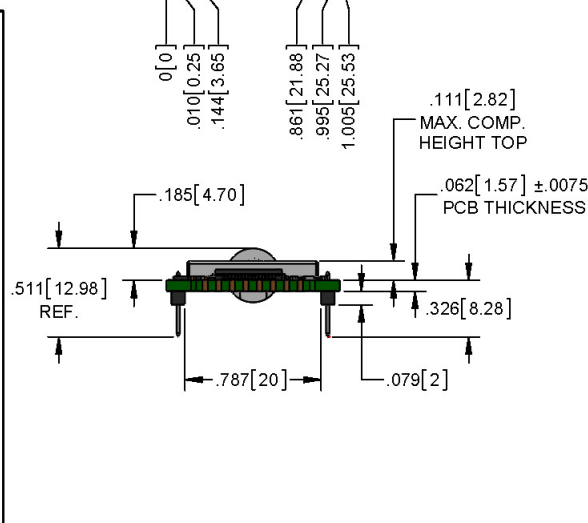
MTDOT-xxx-X1P-U.FL

DIMENSIONS IN In [mm]

MTDOT-xxx-X1-SMA

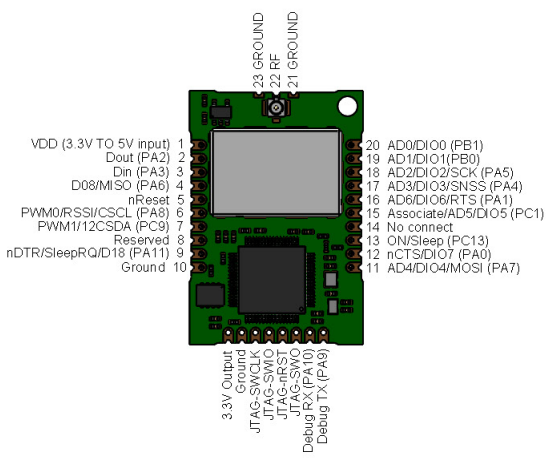
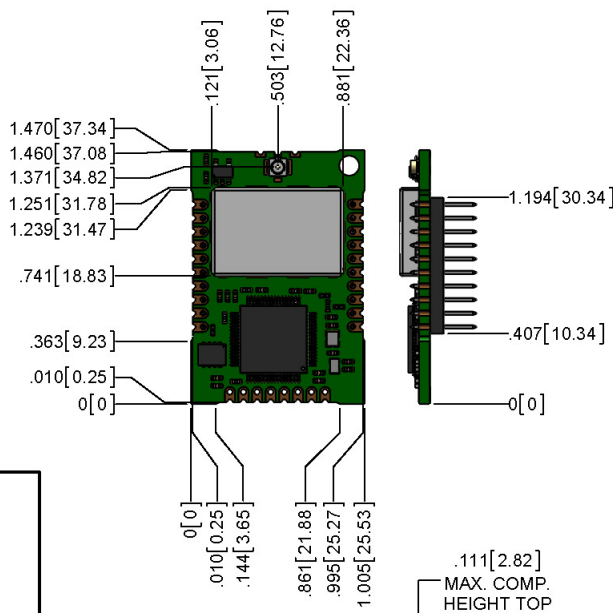
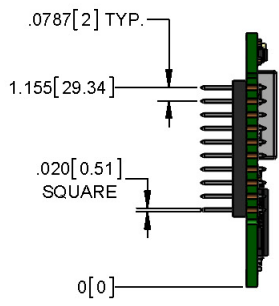
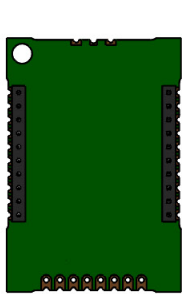
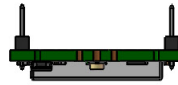
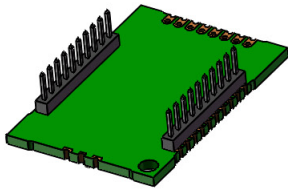
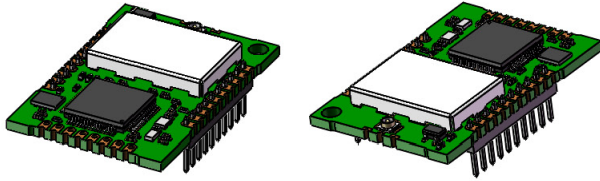


MTDOT-X1-SMA



DIMENSIONS IN In [mm]

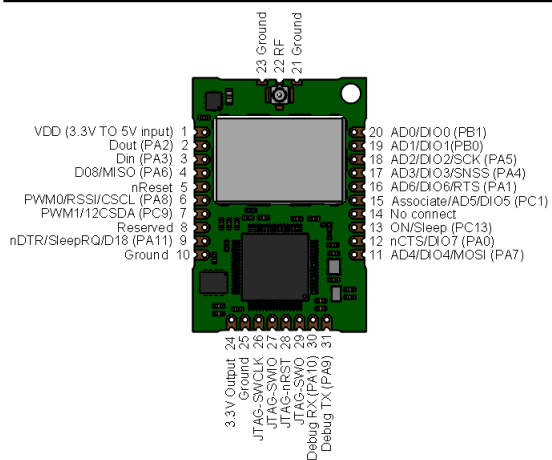
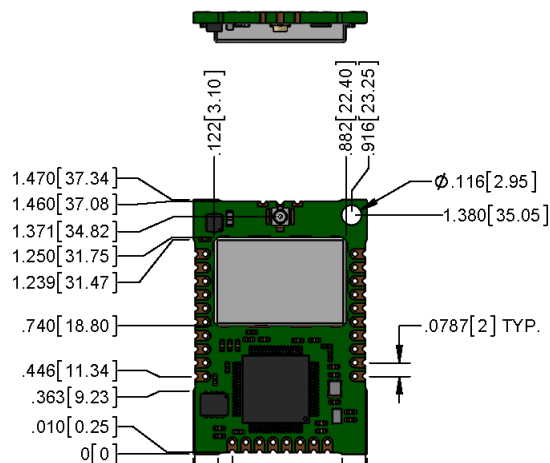
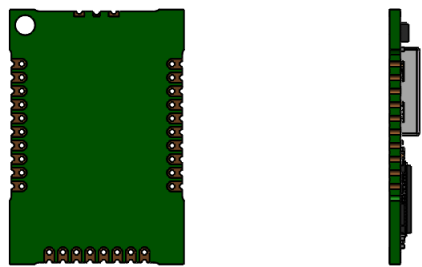
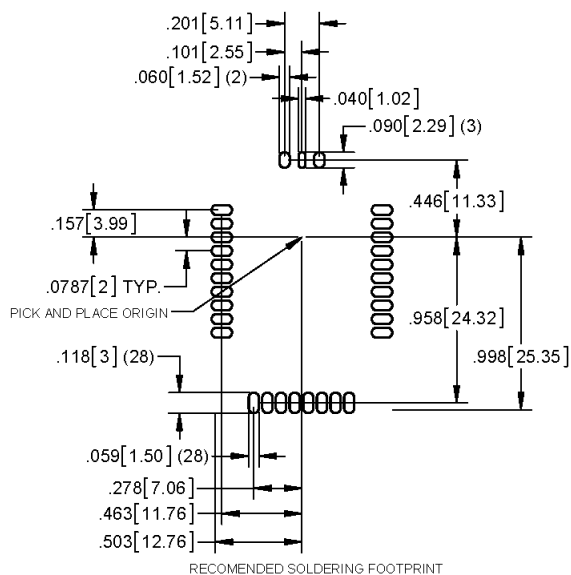
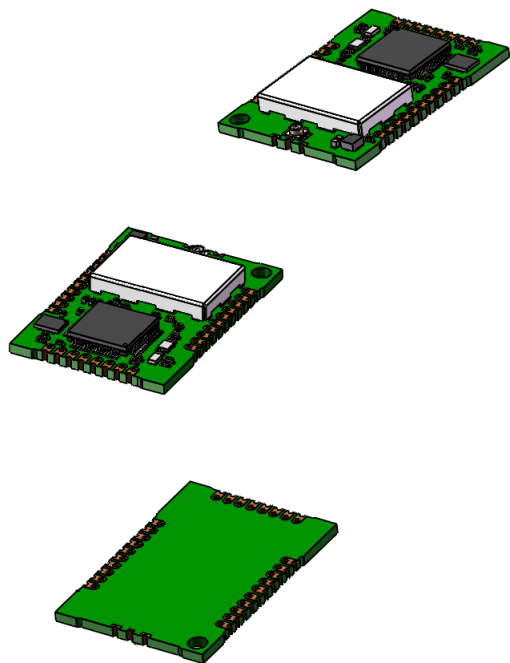
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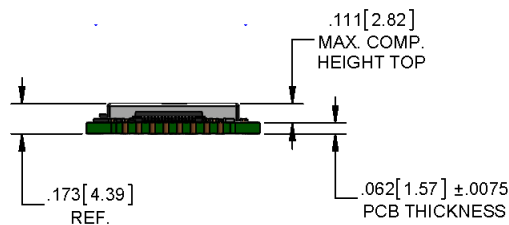
MTDOT-X1-UFL

DIMENSIONS IN In [mm]

MTDOT-xxx-M1-UFL

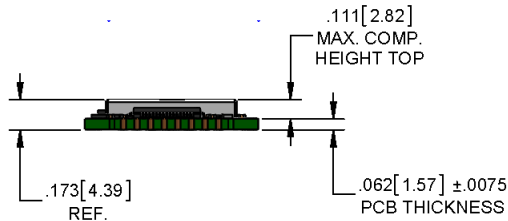
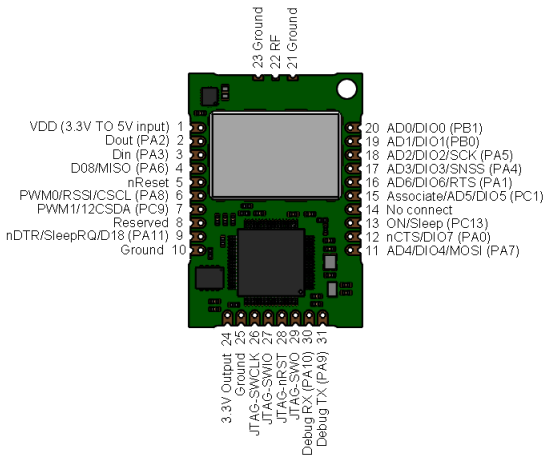
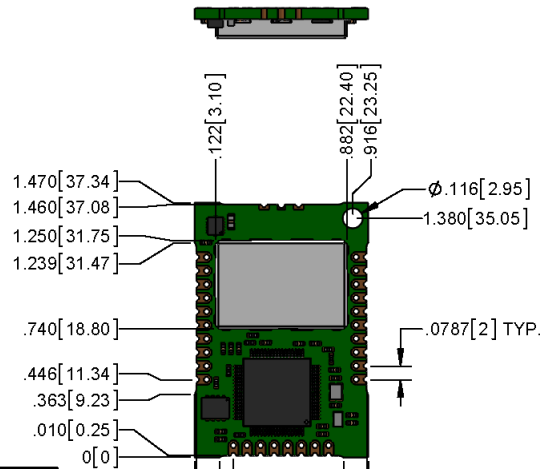
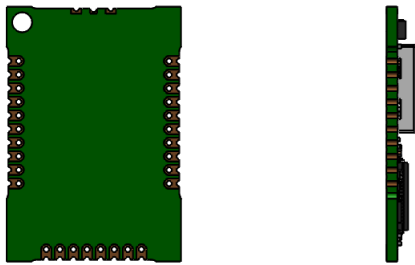
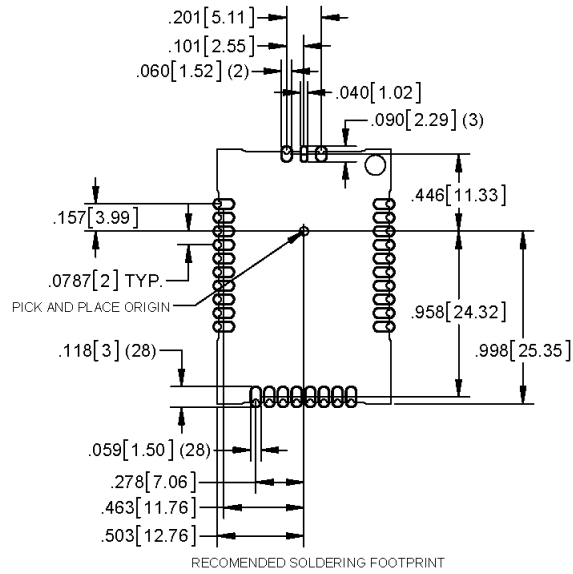
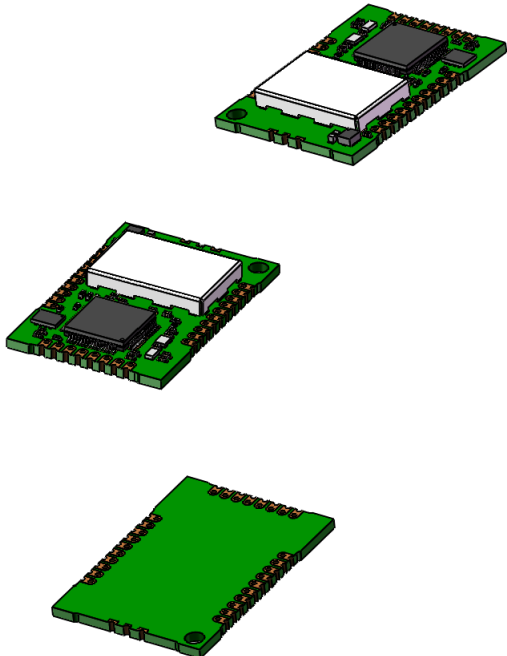


MTDOT-868-M1-UFL
MTDOT-915-M1-UFL



DIMENSIONS IN In [mm]

MTDOT-xxx-M1-TRC



DIMENSIONS IN In [mm]

Chapter 3 Specifications and Pin Information

MTDOT Specifications

Category	Description
General	
Compatibility	LoRaWAN 1.0 specifications
Interfaces	Note that pin functions are multiplexed.
	Up to 16 digital I/O
	Up to 11 analog inputs
	SPI
	I2C
	UART (RX, TX, RTS, CTS)
	USB (OTG full speed)
CPU Performance	
CPU	STM32
Max Clock	100 MHz (configurable to control power use)
Flash Memory	512 KB (400 KB available)
RAM	128 KB
Radio Frequency	
ISM Bands	863 MHz - 868 MHz, 902 MHz - 928 MHz
Physical Description	
Weight ¹	0.2 oz. (5g)
Dimensions	Refer to Mechanical Drawings for Dimensions.
RF Connectors	
-SMA Models	SMA
-UFL Models	U.FL
-Trace Models	Trace Connection
Environment	
Operating Temperature	-40° C to +85° C
Storage Temperature	-40° C to +85° C
Humidity	20%-90% RH, non-condensing
Power Requirements	
Operating Voltage	3.3 V

Category	Description
Certifications and Compliance	
EMC Compliance	EN 300 220-2 V2.4.1:2012
	EN 301 489-03 V1.6.1:2013
Radio Compliance	FCC 15.247:2015
	FCC 15.109:2015
	FCC 15.107:2015
	RSS-210:2010
	ICES-003:2012
	CISPR 22:2008
	EN 300 220-2 V2.4.1:2012
Safety Compliance	UL 60950-1 2nd ED
	cUL 60950-1 2nd ED
	IEC 60950-1 2nd ED AM1 + AM2

¹Weight is for the MTDOT-xxx-X1P-SMA, which is the heaviest model.

Category	Description	
Transmission²		
	North America	EMEA
Max Transmitter Power Output (TPO)	15 dBm	14 dBm
Maximum Receive Sensitivity	-137 dBm	-137 dBm
Link Budget ³	147 dB Point-to-Point	147 dB Point-to-Point
Max Effective Isotropic Radiated Power (EIRP)	22 dBm	10 dBm
Receive Sensitivity		
Spreading Factor	North America Typical Sensitivity⁴	EMEA Typical Sensitivity⁵
6	-111 dBm	-121 dBm
7	-116 dBm	-124 dBm
8	-119 dBm	-127 dBm
9	-122 dBm	-130 dBm
10	-125 dBm	-133 dBm
11	Not Applicable	-135 dBm
12	Not Applicable	-137 dBm

²Using the Pulse Electronics W1063 antenna, described in the *Chapter 4, Antennas*.

³Greater link budget is possible with higher gain antenna.

⁴RFS_L500: RF sensitivity, Long-Range Mode, highest LNA gain, LNA boost, 500 kHz bandwidth using split Rx/Tx path.

⁵RFS_L125: RF sensitivity, Long-Range Mode, highest LNA gain, LNA boost, 125 kHz bandwidth using split Rx/Tx path.

Power Draw

Note:

- Sleep commands are not supported on firmware Version 0.0.14 but will be supported on next firmware release.
- Transmit power measured with MTDOT-915-xx transmitting to a MultiConnect Conduit with an MTAC-LORA-915 accessory card installed.
- mDot was Revision B PCB with firmware Version 0.0.14.
- Idle current measured with the mDot joined with Conduit but idle, no data transferring.
- Transmit power measured while transferring data packets using spread factor 9. Packet size limited to 53 bytes. The Conduit was set to receive packets from and send back to the mDot. A script was run to send the packet 100 times with either 10 or 53 bytes of data, with an average measurement taken during that time.
- For Inrush charge took five separate measurements and recorded the highest observed value.

Voltage	Sleep Mode (Not available on Version 0.0.14 or lower)	Idle current Average (Amps)	Packet Size (Bytes)	Average Current (Amps) at Low Transmit Power Setting (TXP 2)	Average Current (Amps) at Default Transmit Power Setting (TXP 11)	Average Current (Amps) at Maximum Transmit Power Setting (TXP 20)	Total Inrush Charge Measured in Millicoulombs (mC)	Total Inrush Charge Duration during Powerup (InRush Duration)
3.3	Stop mode .50mA	0.032	10	0.026	0.028	0.031	1.14	661uS
	Standby Mode 30.9uA	0.032	53	0.026	0.029	0.041	1.14	661uS
5.0	Stop mode .50mA	0.032	10	0.026	0.028	0.032	1.79	1.24mS
	Standby Mode 33.5uA	0.032	53	0.025	0.028	0.042	1.79	1.24mS

Electrical Characteristics

Signal	Description	Min	Max
Vin Low	Input low level	--	.99
Vin High	Input high level	2.31	--
Vout Low	Output low level	--	.4
Vout High	Output high level	2.9	--
VCC	Standard operating voltage	3.3	5
ICC	Operating current (mA) @5V	--	135
	Operating current (mA) @3.3V	--	200

Pin Information

Using the mbed platform with the Cortex-M4 processor expands your pin functionality options. Refer to the document, mDot Pin Function Mapping, which is available at www.multitech.net/developer/multiconnect-mdot and <https://developer.mbed.org/platforms/MTS-mdot-f411/> for details.

MT Pin	Base Number (Where applicable)	Description
1		VDD (3.3 to 5 V input)
2	PA2	PA_2/XBEE_Dout
3	PA3	PA_3/XBEE_Din
4	PA6	PA_6/XBEE_D08/SPI1_MISO
5		nReset
6	PA8	PA_8/XBEE_PWM0/XBEE_RSSI/I2C_SCL
7	PA9	PA_9/XBEE_PWM1/I2C_SDA
8		Reserved
9	PA11	PA_11/XBEE_nDTR/XBEE_SleepRQ/XBEE_D18
10		Ground
11	PA7	PA_7/XBEE_AD4/XBEE_DIO4/SPI1_MOSI
12	PA0	PA_0/XBEE_nCTS/XBEE_DIO7/LED1
13	PC13	PC_13/XBEE_ON_Sleep
14		No connect
15	PC1	PC_1/XBEE_Associate/XBEE_AD5/XBEE_DIO5

MT Pin	Base Number (Where applicable)	Description
16	PA1	PA_1/XBEE_AD6/XBEE_DIO6/XBEE_RTS
17	PA4	PA_4/XBEE_AD3/XBEE_DIO3/SPI1_CS
18	PA5	PA_5/XBEE_AD2/XBEE_DIO2/SPI1_SCK
19	PB0	PB_0/XBEE_AD1/XBEE_DIO1
20	PB1	PB_1/XBEE_AD0/XBEE_DIO0
21		Ground
22		RF
23		Ground
24		VOOUT (3.3V output)
25		Ground
26	PA14	PA_14/JTAG-SWCLK
27	PA13	PA_13/JTAG-SWIO
28	PB4	PB_4/JTAG-nRST
29	PB3	PB_3/JTAG-SWO
30	PA10	PA_10/Debug RX/
31	PA9	PA_9/Debug TX/USBTX

mDot Pinout Design Notes

Refer to the mechanical drawing for your model for pin locations.

- All pins that go to connectors are directly connected to the processor.
- Reset is the only pin with pull up.
- I/O is 5V tolerant.

mDots allow you to program pins depending on your application:

- **Serial:** Available out of the box. See Serial Pinout Notes for details.
- **Xbee:** Comforms to the Xbee pinout.
- **mbed:** Designed with the mbed STM32F411 RET 64-pin processor, this option provides the most flexibility. For more information about processor capabilities, see the STM32F411 RET datasheet.

Note: To program the mDot, you need an mDot model with programming header., model MTDOT-xx-X1P-SMA

Serial Pinout Notes

Out of the box, these pins are available for serial applications. Refer to the mechanical drawing for your model for pin locations.

- 2 Dout/TX
- 3 Din/RX
- 9 DTR
- 12 CTS
- 13 On/Sleep
- 16 RTS

Serial Settings

When creating a serial connection with an mDot on the developer board, connect a serial cable to the DB-9 connector, open communications software (such as HyperTerminal or TeraTerm), and use the following settings:

- Baud rate = 115,200
- Data bits = 8
- Parity = N
- Stop bits = 1
- Flow control = Off

LoRa

Throughput Rates

Theoretical maximum speeds for LoRa mode with ACKs off are:

- Using spreading factor 7 at 125kHz, the throughput rate is 5470 bps (5.47 kbps).
- Using spreading factor 7 at 500kHz the receiving throughput rate is 21900 bps (21.9 kbps).

Note: Data rates in the LoRaWAN specification vary by geographic region.

Range

Variables effecting the mDot range include TX power, antenna gain, RX sensitivity, fade margin, earth's curvature. Use the following formula to calculate the maximum range:

$$Range_{Miles} = 10^{\left(\frac{TxPower + Antenna\ gain\ total - RX\ Sensitivity - Fade\ Margin - 36.56}{20} - LOG_{10}(F_{MHz})\right)}$$

The following table provides example settings and the theoretical maximum range based on these settings.

Example	18dB Transmit Power for 915 MHz Models	Units	Example 14dB Transmit Power for 868MHz Models
Frequency	915	MHz	868
TX Power	18	dBm	14
TX Antenna Gain	3	dB	3
RX Sensitivity ¹	-120	dBm	-120
RX Antenna Gain	3	dB	3
Fade Margin ²	30	dB	30
Distance	8.14	Miles	5.41
Distance	13.08	Km	8.70

¹RX Sensitivity is set to a conservative -120dBm, but can vary from -117 to -137dBm.

²Fade Margin is set at the worst case of 30dB. Fade margin is an allowance a system designer includes to account for unknown variables. The higher the fade margin, the better the overall link quality will be. With a fade margin set to zero, the link budget is still valid, but only in LOS conditions, which is not practical for most designs. The amount of fade margin to include in a calculation depends on the environment in which you will deploy the system. A fade margin of 12 dBm is good, but a better number would be 20 to 30 dBm.

Chapter 4 Antennas

Antenna System

The LoRa antenna performance depends on the implementation and antenna design. The integration of the antenna system into the product is a critical part of the design process; therefore, it is essential to consider it early so the performance is not compromised. If changes are made to the device's certified antenna system, then recertification will be required.

This radio transmitter IC ID 125A-0054, MTDOT-915 has been approved by Industry Canada to operate with the antenna types listed below with the maximum permissible gain indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Pulse Electronics Antenna

Manufacturer:	Pulse Electronics
Description:	868-915 MHz RP-SMA Antenna, 8"
Model Number:	W1063
MultiTech Part Number:	45009830L

MultiTech ordering information:

Ordering Part Number	Quantity
AN868-915A-1HRA	1
AN868-915A-10HRA	10
AN868-915A-50HRA	50

Antenna Specifications

Category	Description
Frequency Range	868-928 MHz
Impedance	50 Ohms
VSWR	≤ 2.0
Gain	3.0 dBi
Radiation	Omni
Polarization	Vertical

OEM Integration

FCC & IC Information to Consumers

The user manual for the consumer must contain the statements required by the following FCC and IC regulations: 47 C.F.R. 15.19(a)(3), 15.21, 15.105 and RSS-Gen Issue 3, Dec 2010; 7.1.2 and 7.1.3

FCC Grant Notes

The OEM should follow all the grant notes listed below. Otherwise, further testing and device approvals may be necessary.

FCC Definitions

Portable: (§2.1093) — A portable device is defined as a transmitting device designed to be used so that the radiating structure(s) of the device is/are within 20 centimeters of the body of the user.

Mobile: (§2.1091) — A mobile device is defined as a transmitting device designed to be used in other than fixed locations and to generally be used in such a way that a separation distance of at least 20 centimeters is normally maintained between the transmitter's radiating structure(s) and the body of the user or nearby persons.

Actual content pending Grant: *This device is a mobile device with respect to RF exposure compliance. The antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons, and must not be collocated or operate in conjunction with any other antenna or transmitter except in accordance with FCC multi-transmitter product guidelines. Installers and end-users must be provided with specific information required to satisfy RF exposure compliance for installations and final host devices. (See note under Grant Limitations.) Compliance of this device in all final host configurations is the responsibility of the Grantee.*

Note: Host design configurations constituting a device for portable use (<20 cm from human body) require separate FCC/IC approval.

Host Labeling

The following statements are required to be on the host label:

This device contains FCC ID: {Add the FCC ID of the specific device}

This device contains equipment certified under IC ID: {Add the IC ID of the specific device}

For additional labeling requirements, see the product's Labeling Requirements. For the FCC and IC IDs, see specific certificate information in the Regulatory Statement chapter.

Chapter 5 Safety Information

Handling Precautions

To avoid damage due to the accumulation of static charge, use proper precautions when handling any cellular device. Although input protection circuitry has been incorporated into the devices to minimize the effect of static build-up, use proper precautions to avoid exposure to electronic discharge during handling and mounting the device.

Radio Frequency (RF) Safety

Due to the possibility of radio frequency (RF) interference, it is important that you follow any special regulations regarding the use of radio equipment. Follow the safety advice given below.

- Operating your device close to other electronic equipment may cause interference if the equipment is inadequately protected. Observe any warning signs and manufacturers' recommendations.
- Different industries and businesses restrict the use of cellular devices. Respect restrictions on the use of radio equipment in fuel depots, chemical plants, or where blasting operations are in process. Follow restrictions for any environment where you operate the device.
- Do not place the antenna outdoors.
- Switch OFF your wireless device when in an aircraft. Using portable electronic devices in an aircraft may endanger aircraft operation, disrupt the cellular network, and is illegal. Failing to observe this restriction may lead to suspension or denial of cellular services to the offender, legal action, or both.
- Switch OFF your wireless device when around gasoline or diesel-fuel pumps and before filling your vehicle with fuel.
- Switch OFF your wireless device in hospitals and any other place where medical equipment may be in use.

Sécurité relative aux appareils à radiofréquence (RF)

À cause du risque d'interférences de radiofréquence (RF), il est important de respecter toutes les réglementations spéciales relatives aux équipements radio. Suivez les conseils de sécurité ci-dessous.

- Utiliser l'appareil à proximité d'autres équipements électroniques peut causer des interférences si les équipements ne sont pas bien protégés. Respectez tous les panneaux d'avertissement et les recommandations du fabricant.
- Certains secteurs industriels et certaines entreprises limitent l'utilisation des appareils cellulaires. Respectez ces restrictions relatives aux équipements radio dans les dépôts de carburant, dans les usines de produits chimiques, ou dans les zones où des dynamitages sont en cours. Suivez les restrictions relatives à chaque type d'environnement où vous utiliserez l'appareil.
- Ne placez pas l'antenne en extérieur.
- Éteignez votre appareil sans fil dans les avions. L'utilisation d'appareils électroniques portables en avion est illégale: elle peut fortement perturber le fonctionnement de l'appareil et désactiver le réseau cellulaire. S'il ne respecte pas cette consigne, le responsable peut voir son accès aux services cellulaires suspendu ou interdit, peut être poursuivi en justice, ou les deux.
- Éteignez votre appareil sans fil à proximité des pompes à essence ou de diesel avant de remplir le réservoir de votre véhicule de carburant.

- Éteignez votre appareil sans fil dans les hôpitaux ou dans toutes les zones où des appareils médicaux sont susceptibles d'être utilisés.

Interference with Pacemakers and Other Medical Devices

Potential interference

Radiofrequency energy (RF) from cellular devices can interact with some electronic devices. This is electromagnetic interference (EMI). The FDA helped develop a detailed test method to measure EMI of implanted cardiac pacemakers and defibrillators from cellular devices. This test method is part of the Association for the Advancement of Medical Instrumentation (AAMI) standard. This standard allows manufacturers to ensure that cardiac pacemakers and defibrillators are safe from cellular device EMI.

The FDA continues to monitor cellular devices for interactions with other medical devices. If harmful interference occurs, the FDA will assess the interference and work to resolve the problem.

Precautions for pacemaker wearers

If EMI occurs, it could affect a pacemaker in one of three ways:

- Stop the pacemaker from delivering the stimulating pulses that regulate the heart's rhythm.
- Cause the pacemaker to deliver the pulses irregularly.
- Cause the pacemaker to ignore the heart's own rhythm and deliver pulses at a fixed rate.

Based on current research, cellular devices do not pose a significant health problem for most pacemaker wearers. However, people with pacemakers may want to take simple precautions to be sure that their device doesn't cause a problem.

- Keep the device on the opposite side of the body from the pacemaker to add extra distance between the pacemaker and the device.
- Avoid placing a turned-on device next to the pacemaker (for example, don't carry the device in a shirt or jacket pocket directly over the pacemaker).

Device Maintenance

When maintaining your device:

- Do not attempt to disassemble the device. There are no user serviceable parts inside.
- Do not expose your device to any extreme environment where the temperature or humidity is high.
- Do not expose the device to water, rain, or spilled beverages. It is not waterproof.
- Do not place the device alongside computer discs, credit or travel cards, or other magnetic media. The information contained on discs or cards may be affected by the device.
- Using accessories, such as antennas, that MultiTech has not authorized or that are not compliant with MultiTech's accessory specifications may invalidate the warranty.

If the device is not working properly, contact MultiTech Technical Support.

User Responsibility

Respect all local regulations for operating your wireless device. Use the security features to block unauthorized use and theft.

Chapter 6 Regulatory Information

EMC, Safety, and R&TTE Directive Compliance



The CE mark is affixed to this product to confirm compliance with the following European Community Directives:

Council Directive 2004/108/EC of 15 December 2004 on the approximation of the laws of Member States relating to electromagnetic compatibility;

and

Council Directive 2006/95/EC of 12 December 2006 on the harmonization of the laws of Member States relating to electrical equipment designed for use within certain voltage limits;

and

Council Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment;

and

Council Directive 1999/5/EC of 9 March 1999 on radio equipment and telecommunications terminal equipment and the mutual recognition of their conformity.

47 CFR Part 15 Regulation Class B Devices

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

Warning: Changes or modifications to this unit not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Notice

Per FCC 15.19(a)(3) and (a)(4) This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

FCC Grant

FCC Part 15

FCC Identifier:	AU792U13A16857
Equipment Class:	Digital Transmission System
Notes:	MTDOT-915
FCC Rule Parts:	15C
Approval:	Single Modular
Frequency Range:	902.3-914.9
Output Watts:	0.0772

Output power is conducted. This transmitter is a hybrid per FCC 15.247(f) and FCC KDB 453039. The antenna(s) used for this transmitter must be installed to provide a separation distance of at least 20 cm from all persons and must not be collocated or operating in conjunction with any other antenna or transmitter within a host device, except in accordance with FCC multi-transmitter product procedures. End-users and installers must be provided with antenna installation instructions and transmitter operating conditions for satisfying RF exposure compliance.

FCC Notice

The MTDOT-x family of products are open development based products that contain a sub ghz radio technology. MultiTech has certified for compliance with US and Foreign compliance bodies including FCC, R&TTE and others. (e.g. FCC 15.247:2015 & IC RSS-210:2010)

MultiTech provides software code meant to operate the radio to a level that maintains compliance with the operating modes under which these radio devices were certified. To ensure this level of compliance, the software code is provided in binary form only. Users are prohibited from making any changes that affect the operation of the radio performance. Accessing or controlling the radio through any means other than the provided binary software will require the user to obtain their own intentional radiator license from the certification body governing their locality, as all precertification provided with mDot will have been made invalid.

Industry Canada Class B Notice

This Class B digital apparatus meets all requirements of the Canadian Interference-Causing Equipment Regulations.

Cet appareil numérique de la classe B respecte toutes les exigences du Règlement Canadien sur le matériel brouilleur.

This device complies with Industry Canada RSS Appliance radio exempt from licensing. The operation is permitted for the following two conditions:

1. the device may not cause harmful interference, and
2. the user of the device must accept any interference suffered, even if the interference is likely to jeopardize the operation.

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes:

1. l'appareil ne doit pas produire de brouillage, et

2. l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Industry Canada

Certification Number/No. de Certification	125A-0054
Type of Radio Equipment/Genre de Matériel	Spread Spectrum/Digital Device (902-928MHz)/ Modular Approval/Approbation modulaire
Model/Modèle	MTDOT-915

Specification/Charge	Issue/Édition	From Frequency/Départ des Fréquences	To Frequency/À Fréquences	Emission Designation/Désignation D'émission	Minimum Power	Maximum Power
RSS247	1.0	902.3 MHz	914.9 MHz	GXDXX	77.2 mW	77.2 mW

Certification of equipment means only that the equipment has met the requirements of the above noted specification. License applications, where applicable to use certified equipment, are acted on accordingly by the Industry Canada issuing office and will depend on the existing radio environment, service and location of operation. This certificate is issued on condition that the holder complies and will continue to comply with the requirements and procedures issued by Industry Canada. The equipment for which this certificate is issued shall not be manufactured, imported distributed, leased, offered for sale or sold unless the equipment complies with the applicable technical specifications and procedures issued by Industry Canada.

La certification du matériel signifie seulement que le matériel a satisfait aux exigences de la norme indiquée ci-dessus. Les demandes de licences nécessaires pour l'utilisation du matériel certifié sont traitées en conséquence par le bureau de délivrance d'Industrie Canada et dépendent des conditions radio ambiantes, du service et de l'emplacement d'exploitation. Le présent certificat est délivré à la condition que le titulaire satisfasse et continue de satisfaire aux exigences et aux procédures d'Industrie Canada. Le matériel à l'égard duquel le présent certificat est délivré ne doit pas être fabriqué, importé, distribué, loué, mis en vente ou vendu à moins d'être conforme aux procédures et aux spécifications techniques applicable publiées par Industrie Canada.

Chapter 7 Environmental Notices

Waste Electrical and Electronic Equipment Statement

Note: This statement may be used in documentation for your final product applications.

WEEE Directive

The WEEE Directive places an obligation on EU-based manufacturers, distributors, retailers, and importers to take-back electronics products at the end of their useful life. A sister directive, ROHS (Restriction of Hazardous Substances) complements the WEEE Directive by banning the presence of specific hazardous substances in the products at the design phase. The WEEE Directive covers all MultiTech products imported into the EU as of August 13, 2005. EU-based manufacturers, distributors, retailers and importers are obliged to finance the costs of recovery from municipal collection points, reuse, and recycling of specified percentages per the WEEE requirements.

Instructions for Disposal of WEEE by Users in the European Union

The symbol shown below is on the product or on its packaging, which indicates that this product must not be disposed of with other waste. Instead, it is the user's responsibility to dispose of their waste equipment by handing it over to a designated collection point for the recycling of waste electrical and electronic equipment. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment for recycling, please contact your local city office, your household waste disposal service or where you purchased the product.

July, 2005



REACH Statement

Registration of Substances

After careful review of the legislation and specifically the definition of an “article” as defined in EC Regulation 1907/2006, Title II, Chapter 1, Article 7.1(a)(b), it is our current view Multi-Tech Systems, Inc. products would be considered as “articles”. In light of the definition in § 7.1(b) which requires registration of an article only if it contains a regulated substance that “is intended to be released under normal or reasonably foreseeable conditions of use,” Our analysis is that Multi-Tech Systems, Inc. products constitute nonregisterable articles for their intended and anticipated use.

Substances of Very High Concern (SVHC)

Per the candidate list of Substances of Very High Concern (SVHC) published October 28, 2008 we have reviewed these substances and certify the Multi-Tech Systems, Inc. products are compliant per the EU “REACH” requirements of less than 0.1% (w/w) for each substance. If new SVHC candidates are published by the European Chemicals Agency, and relevant substances have been confirmed, that exceeds greater than 0.1% (w/w), Multi-Tech Systems, Inc. will provide updated compliance status.

Multi-Tech Systems, Inc. also declares it has been duly diligent in ensuring that the products supplied are compliant through a formalized process which includes collection and validation of materials declarations and selective materials analysis where appropriate. This data is controlled as part of a formal quality system and will be made available upon request.

Restriction of the Use of Hazardous Substances (RoHS)



Multi-Tech Systems, Inc.

Certificate of Compliance

2011/65/EU

Multi-Tech Systems, Inc. confirms that its embedded products comply with the chemical concentration limitations set forth in the directive 2011/65/EU of the European Parliament (Restriction of the use of certain Hazardous Substances in electrical and electronic equipment - RoHS).

These MultiTech products do not contain the following banned chemicals¹:

- Lead, [Pb] < 1000 PPM
- Mercury, [Hg] < 1000 PPM
- Hexavalent Chromium, [Cr+6] < 1000 PPM
- Cadmium, [Cd] < 100 PPM
- Polybrominated Biphenyl, [PBB] < 1000 PPM
- Polybrominated Diphenyl Ether, [PBDE] < 1000 PPM

Environmental considerations:

- Moisture Sensitivity Level (MSL) =1
- Maximum Soldering temperature = 260C (in SMT reflow oven)

¹Lead usage in some components is exempted by the following RoHS annex, therefore higher lead concentration would be found in some modules (>1000 PPM);

- Resistors containing lead in a glass or ceramic matrix compound.

Information on HS/TS Substances According to Chinese Standards

In accordance with China's Administrative Measures on the Control of Pollution Caused by Electronic Information Products (EIP) # 39, also known as China RoHS, the following information is provided regarding the names and concentration levels of Toxic Substances (TS) or Hazardous Substances (HS) which may be contained in Multi-Tech Systems Inc. products relative to the EIP standards set by China's Ministry of Information Industry (MII).

Hazardous/Toxic Substance/Elements

Name of the Component	Lead (PB)	Mercury (Hg)	Cadmium (CD)	Hexavalent Chromium (CR6+)	Polybrominated Biphenyl (PBB)	Polybrominated Diphenyl Ether (PBDE)
Printed Circuit Boards	O	O	O	O	O	O
Resistors	X	O	O	O	O	O
Capacitors	X	O	O	O	O	O
Ferrite Beads	O	O	O	O	O	O
Relays/Opticals	O	O	O	O	O	O
ICs	O	O	O	O	O	O
Diodes/ Transistors	O	O	O	O	O	O
Oscillators and Crystals	X	O	O	O	O	O
Regulator	O	O	O	O	O	O
Voltage Sensor	O	O	O	O	O	O
Transformer	O	O	O	O	O	O
Speaker	O	O	O	O	O	O
Connectors	O	O	O	O	O	O
LEDs	O	O	O	O	O	O
Screws, Nuts, and other Hardware	X	O	O	O	O	O
AC-DC Power Supplies	O	O	O	O	O	O
Software /Documentation CDs	O	O	O	O	O	O
Booklets and Paperwork	O	O	O	O	O	O
Chassis	O	O	O	O	O	O

X Represents that the concentration of such hazardous/toxic substance in all the units of homogeneous material of such component is higher than the SJ/Txxx-2006 Requirements for Concentration Limits.

O Represents that no such substances are used or that the concentration is within the aforementioned limits.

Information on HS/TS Substances According to Chinese Standards (in Chinese)

依照中国标准的有毒有害物质信息

根据中华人民共和国信息产业部 (MII) 制定的电子信息产品 (EIP) 标准—中华人民共和国《电子信息产品污染控制管理办法》(第 39 号), 也称作中国 RoHS, 下表列出了 Multi-Tech Systems, Inc. 产品中可能含有的有毒物质 (TS) 或有害物质 (HS) 的名称及含量水平方面的信息。

有害/有毒物质/元素

成分名称	铅 (PB)	汞 (Hg)	镉 (CD)	六价铬 (CR6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷电路板	O	O	O	O	O	O
电阻器	X	O	O	O	O	O
电容器	X	O	O	O	O	O
铁氧体磁环	O	O	O	O	O	O
继电器/光学部件	O	O	O	O	O	O
ICs	O	O	O	O	O	O
二极管/晶体管	O	O	O	O	O	O
振荡器和晶振	X	O	O	O	O	O
调节器	O	O	O	O	O	O
电压传感器	O	O	O	O	O	O
变压器	O	O	O	O	O	O
扬声器	O	O	O	O	O	O
连接器	O	O	O	O	O	O
LEDs	O	O	O	O	O	O
螺丝、螺母以及其它五金件	X	O	O	O	O	O
交流-直流电源	O	O	O	O	O	O
软件/文档 CD	O	O	O	O	O	O
手册和纸页	O	O	O	O	O	O
底盘	O	O	O	O	O	O

X 表示所有使用类似材料的设备中有害/有毒物质的含量水平高于 SJ/Txxx-2006 限量要求。

O 表示不含该物质或者该物质的含量水平在上述限量要求之内。

Chapter 8 Labels

Approvals and Certification

In most cases, when integrated and used with an antenna system that was part of the MultiTech modem certification, additional approvals or certifications are not required for the device you develop as long as the following are met.

- **PTCRB Requirements:** The antenna system cannot be altered.
- **Model Identification:** The MultiTech model identification allows the carrier to verify the modem as one of its approved models. This information is located on the modem's label below the bar code.

Example Labels

Note: Actual labels vary depending on the regulatory approval markings and content.

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

The label shown is not than actual size.

- 1 - MultiTech Model Identification.
- 2 - MultiTech Ordering Part Number.
- 3 - Device Node Number.

Example North America Package Label



Example EMEA Package Label



North America Device Label



EMEA Device Label



Chapter 9 Developer Kit Overview

Developer Board Overview

MultiTech offers Developer Kits for prototyping and developing with the mDot:

- **MTUKD2-ST-CELL** is a full developer board and kit compatible with several MultiTech devices.
- **MTUDK2-ST-MDOT** is a scaled down version of the developer board and kit for the mDot.

Use either developer kit to streamline your development efforts and evaluate your products and applications. Easily plug in your communications device and use the developer kit for testing, programming and evaluation.

Note: Developer information in this section applies to either developer kit when used with an mDot; however, the illustrations show the MTUDK2-ST-MDOT model.

Developer Board Features

- USB and serial interfaces
- USB port for mbed development environment
- RS-232 DB-9 connector for serial interface
- Arduino shield socket

MTUDK2-ST-MDOT Developer Kit Contents

The MTUDK2-ST-MDOT Developer Kit includes the following:

Developer Board	1 - MTUDK 2.0 mDot Developer Board
Cables	1 - Micro USB Cable
	1 - RSMA-U.FL Antenna Cables (attached to developer board)
Antennas	1 - 868-945 MHz Antenna
Customer Notices	Quick Start
Additional	One promotional screwdriver

MTUDK2-ST-CELL Developer Kit Contents

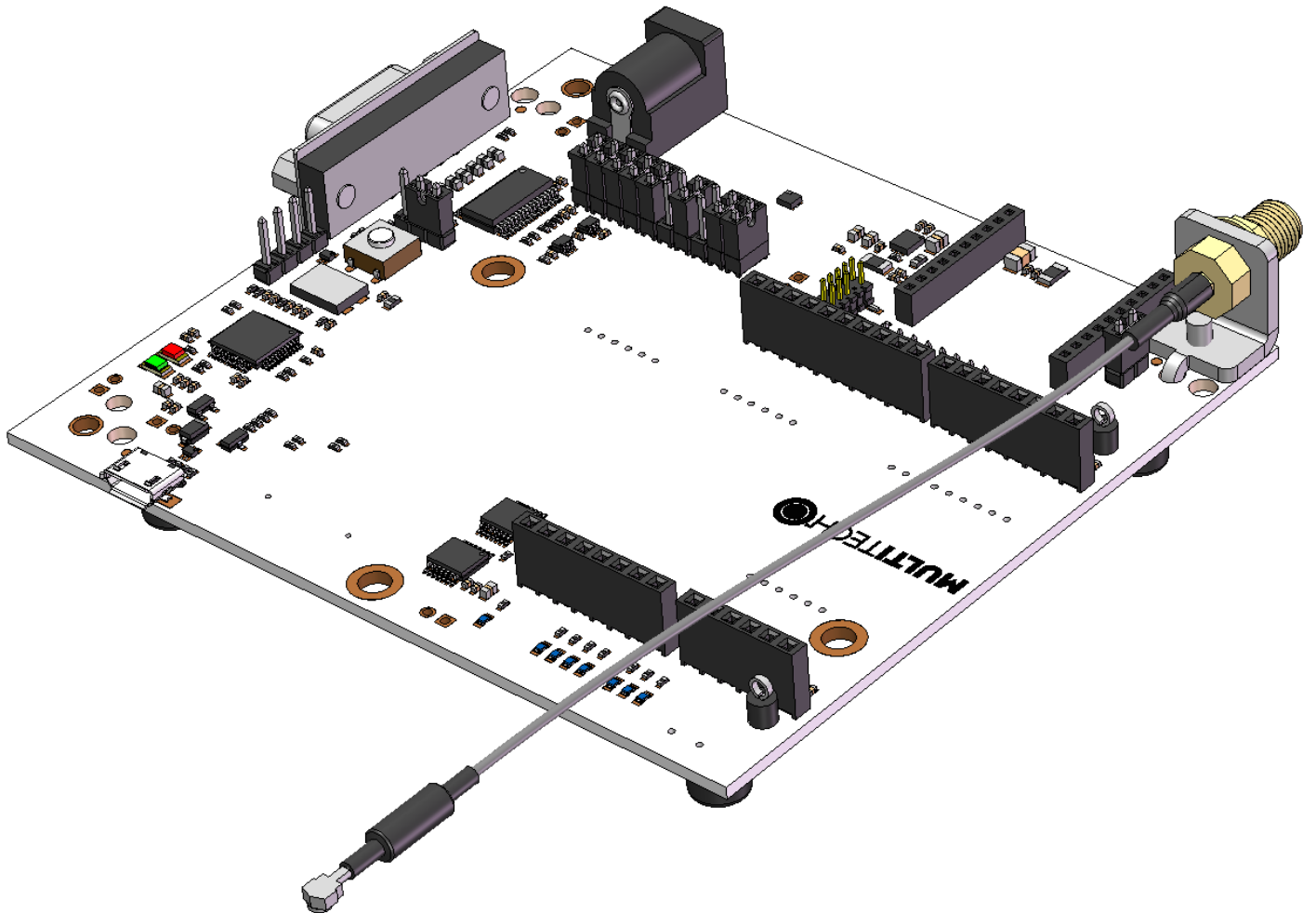
The MTUDK2-ST-CELL Developer Kit includes the following:

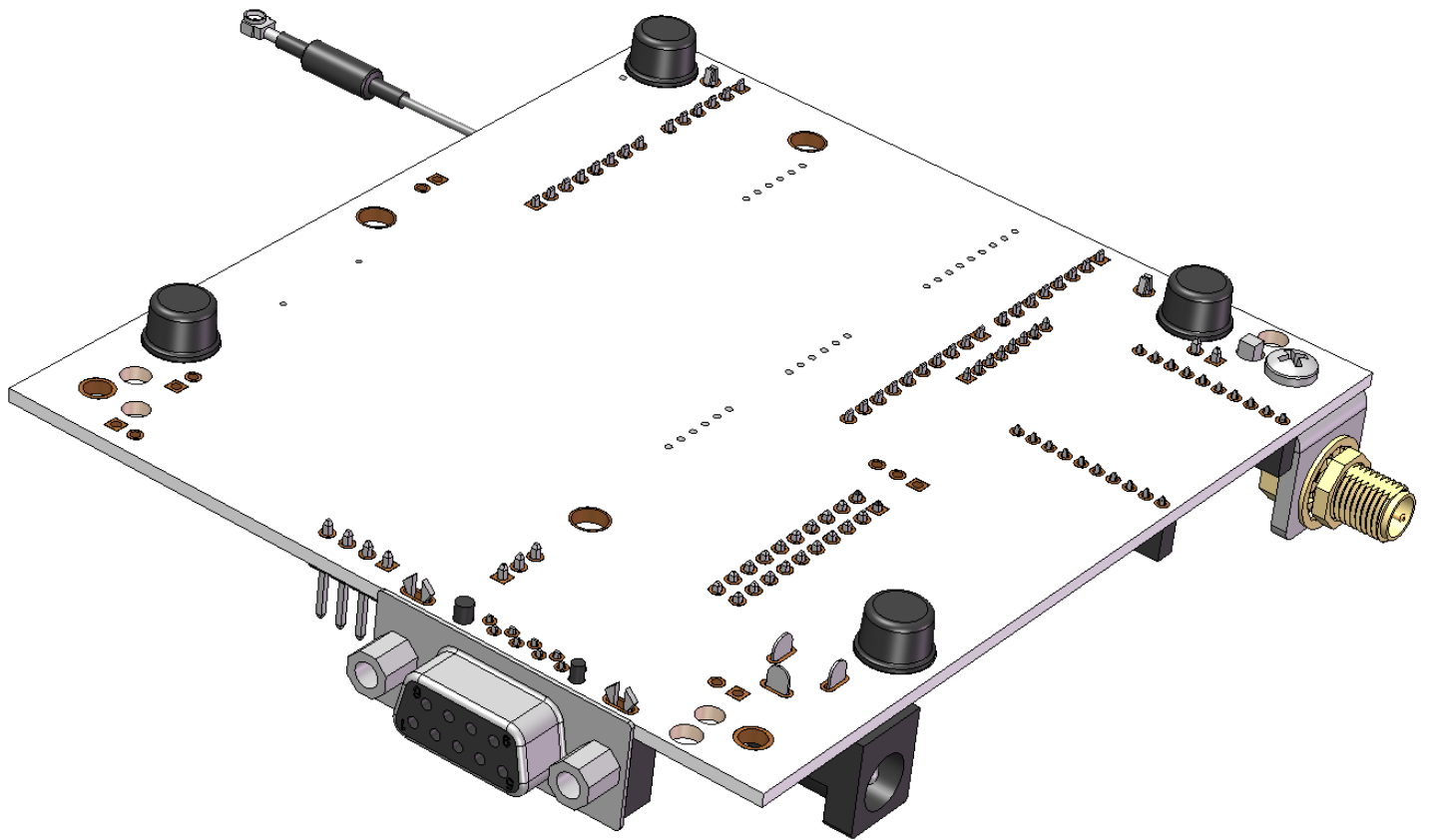
Developer Board	1 - MTUDK 2.0 Cell Developer Board
Power Supply	1 - 100-240V 9V-1.7A power supply with removable blades
	1 - NAM blade/plug,
	1 - EURO blade/plug
	1 - UK blade/plug
	1 - AU/NZ blade/plug

Cables	1 - Micro USB Cable
	3 - SMA-U.FL Antenna Cables (attached to developer board)
Antennas	1 - 3.3V magnetic GPS Antenna
	2 - 700-2600 MHz Antennas
Customer Notices	Quick Start
Additional	One promotional screwdriver

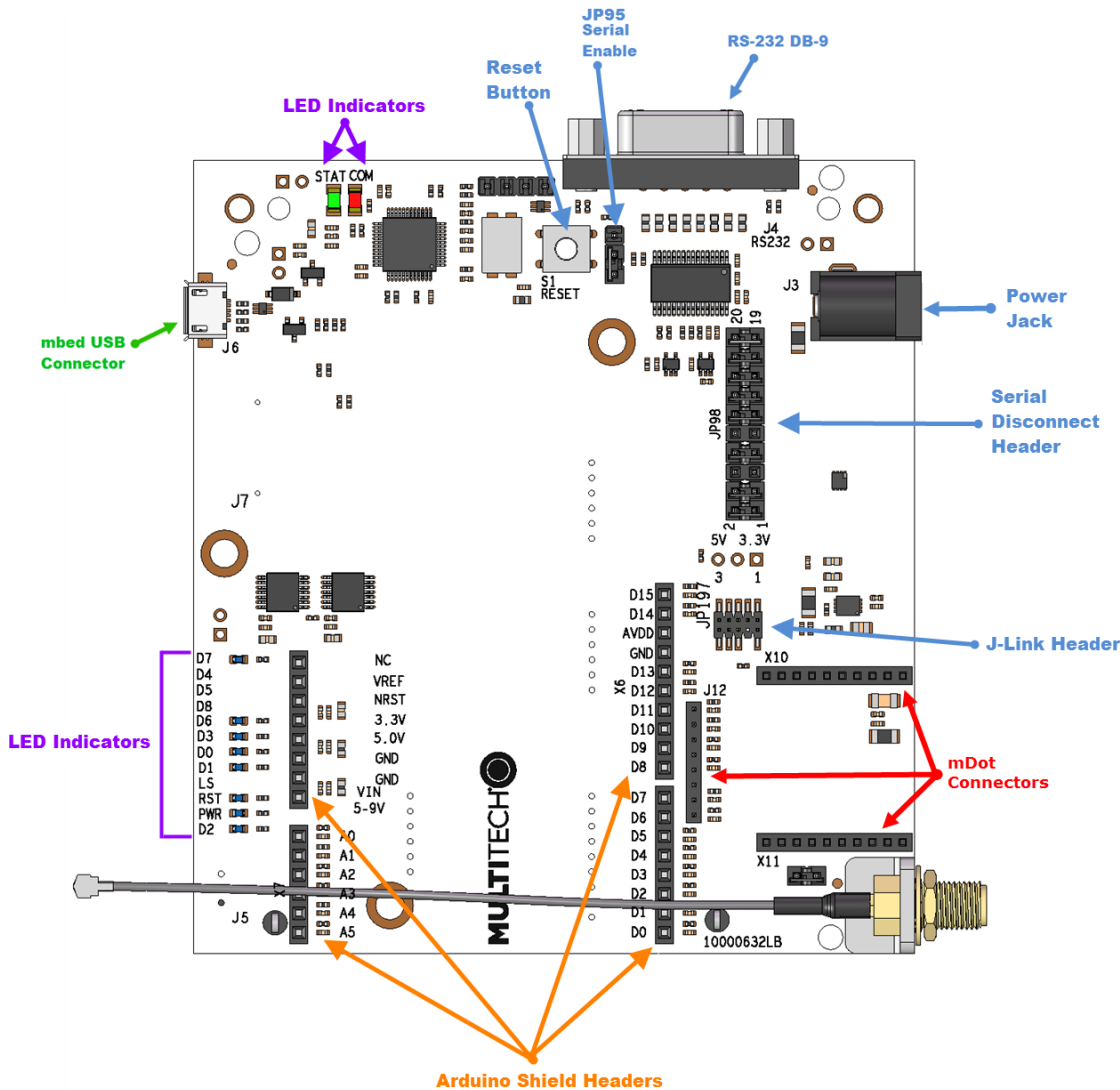
Chapter 10 Board Components

Developer Board





Developer Board Connectors



Board Components

Label	Description
J4	RS232 DB-9 Serial Connector , used to access the mDot AT command interface.
J6	mbed USB Connector, attaches to the ST Micro controller. This provides access to two interfaces, one used to program the mDot and the other for debug messages.
JP98	Serial Disconnect Header. Pins D0-D8 are connected to the Arduino headers and the DB9 serial port. Remove these jumpers to disconnect from the RS232 transceiver chip.
JP197	J-Link Header, used for JTAG access to the mDot. This requires installing resistors R94-96 & 98 and removing R88-990 & 92. See <i>Chapter 12 Developer Board Schematics</i> .
S1	Reset Button.

Label	Description
X6	Arduino Shield Connector.
X7	Arduino Shield Connector.
X8	Arduino Shield Connector.
X9	Arduino Shield Connector.
X10	MTDOT Connector.
X11	MTDOT Connector.
J12	MTDOT Programming Header.

LED Indicators

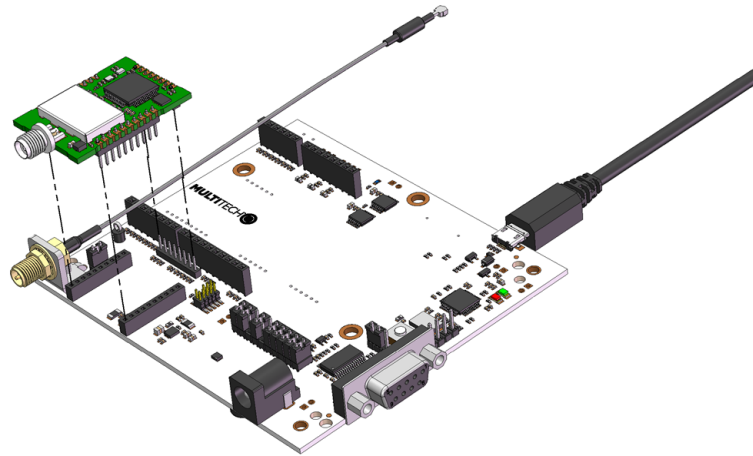
Label	LED	Location
STAT	LED1	Same side as RS-232 DB-9 connector
COM	LED2	Same side as RS-232 DB-9 connector
D7	LED3	Across the mDot connectors.
D6	LED7	Directly across from the mDot connectors.
D3	LED8	Directly across from the mDot connectors.
D0	LED9	Directly across from the mDot connectors.
D1	LED10	Directly across from the mDot connectors.
RST	LED12	Directly across from the mDot connectors.
PWR	LED13	Directly across from the mDot connectors.
D2	LED14	Directly across from the mDot connectors.

Chapter 11 Developer Board Installation

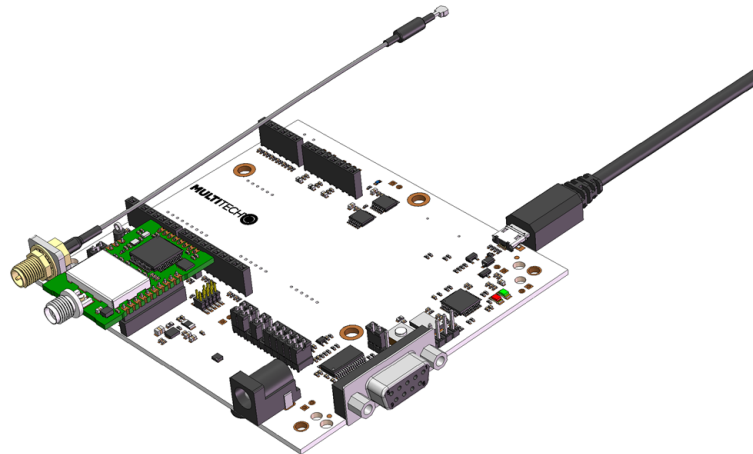
Installing an mDot on the Developer Board

To install an mDot on the Developer Board:

1. Align the mDot with the developer board as shown.



2. Gently press the mDot into the connectors.



Arduino Shield

mDot Arduino Pins

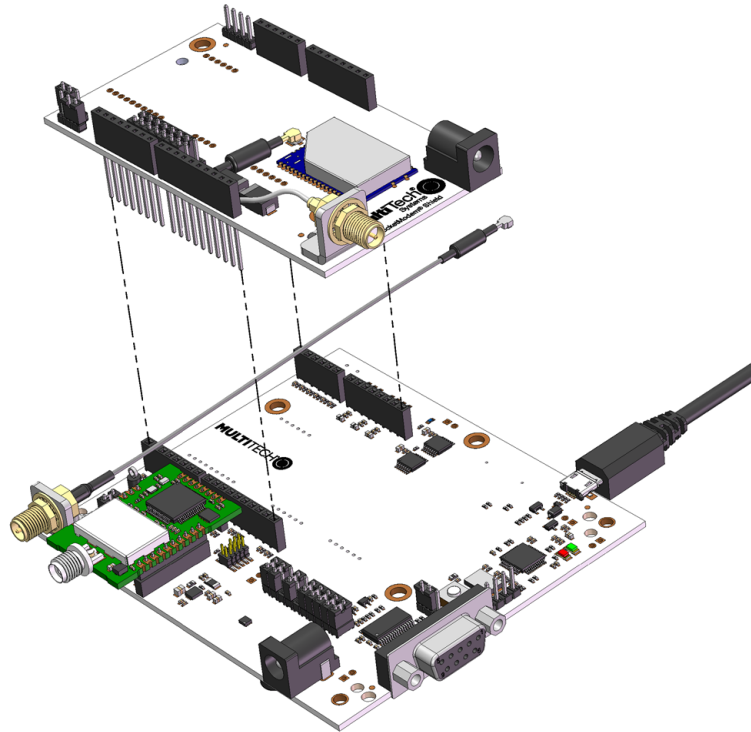
Signals (module pin) micro pin		Arduino Shield				Signals (module pin) micro pin	
				D15		PWM0/RSSI/I2CSCL (6) PA8	
				D14		PWM1/I2CSDA (7) PC9	
				AVDD		3.3V	
				GND		Ground	
			NC	D13	X6	AD2/DIO2/SCK (18) PA5	
3.3V			VREF	D12		DO8/MISO (4) PA6	
nReset, from pushbutton			nRST	D11		AD4/DIO4/MOSI (11) PA7	
3.3V			3.3V	D10		AD3/DIO3/SNSS (17) PA4	
5.0V	X9		5.0V	D9		no connect	
Ground			GND	D8		no connect	
Ground			GND				
5-9V input from J3			VIN	D7		nDTR/SleepRQ/DI8 (9) PA11	
				D6		nRTS/AD6/DIO6 (16) PA1	
AD0/DIO0 (20) PB1			A0	D5		no connect	
AD1/DIO1 (19) PB0			A1	D4	X8	no connect	
Associate/AD5/DIO5 (15) PC1	X7		A2	D3		nCTS/DIO7 (12) PA0	
no connect			A3	D2		ON/nSleep (13) PC13	
no connect			A4	D1		Dout (2) PA2	
no connect			A5	D0		Din (3) PA3	

Installing an Arduino Shield with an mDot

Note: When using an Arduino Shield with an mDot, install the mDot on the developer board before installing the Arduino shield.

To use an Arduino Shield with an mDot:

1. Disable the developer card's serial port by removing jumper from JP95.
 - Jumper pins 1-2: Disable U5 on USB VCC high.
 - Jumper pins 2-3: U5 always disabled.
 - Default jumper position is on pins 1-2.
2. Align the Arduino Shield on the developer board as shown.



RSMA to U.FL Cables

The developer kit includes one 4.5" RSMA to U.FL cables which is preinstalled on the developer board.

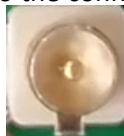


Connecting an Antenna through the Developer Board Connectors

Depending on the mDot model, either connect the antenna directly to the mDot or through the RSMA-to-U.FL antenna cable on the developer board.

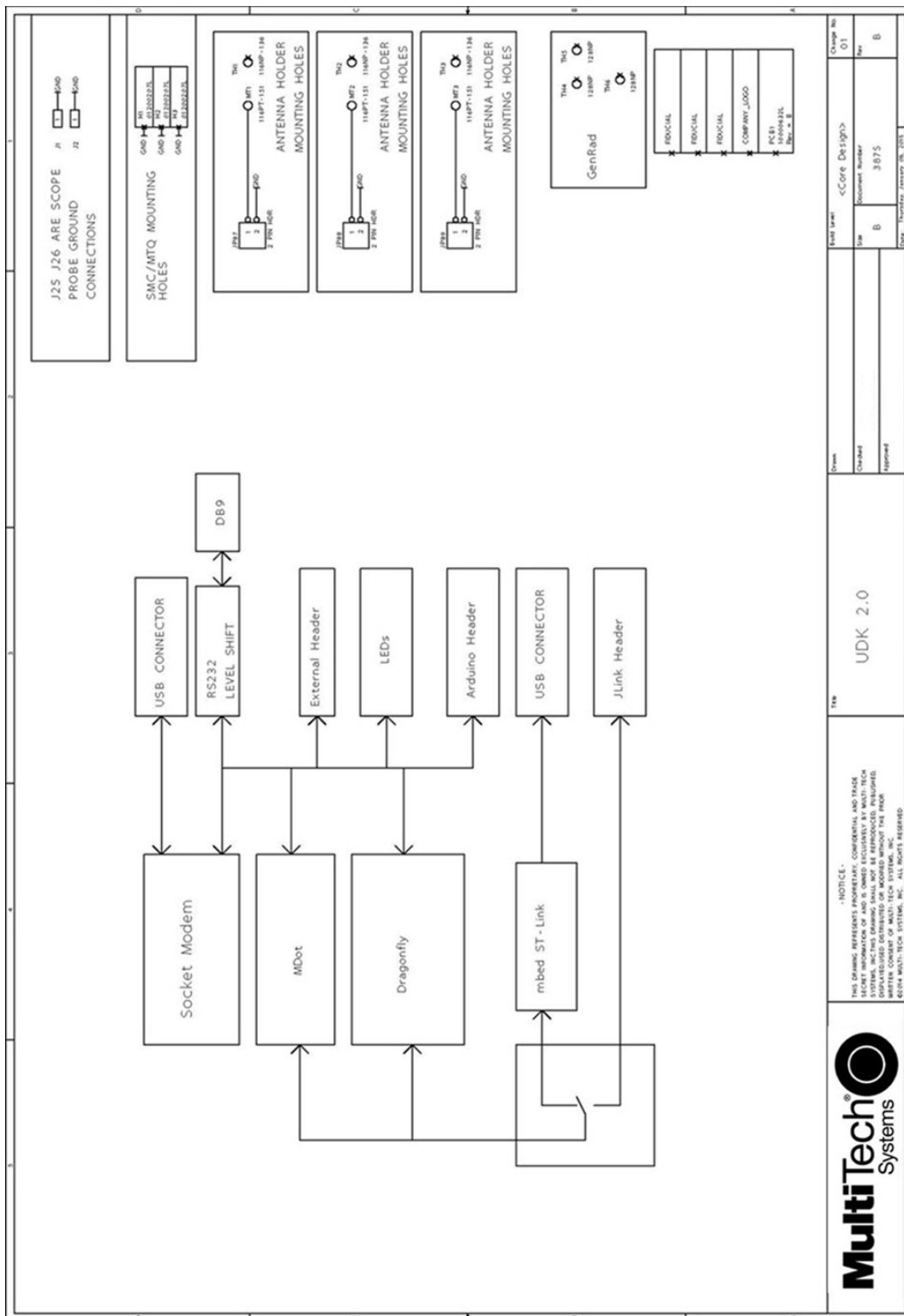
To connect an antenna to the device through the developer board :

1. Finger tighten the antenna to the SMA connector.
2. Attach the U.FL connector from the cable to the connector on the device.

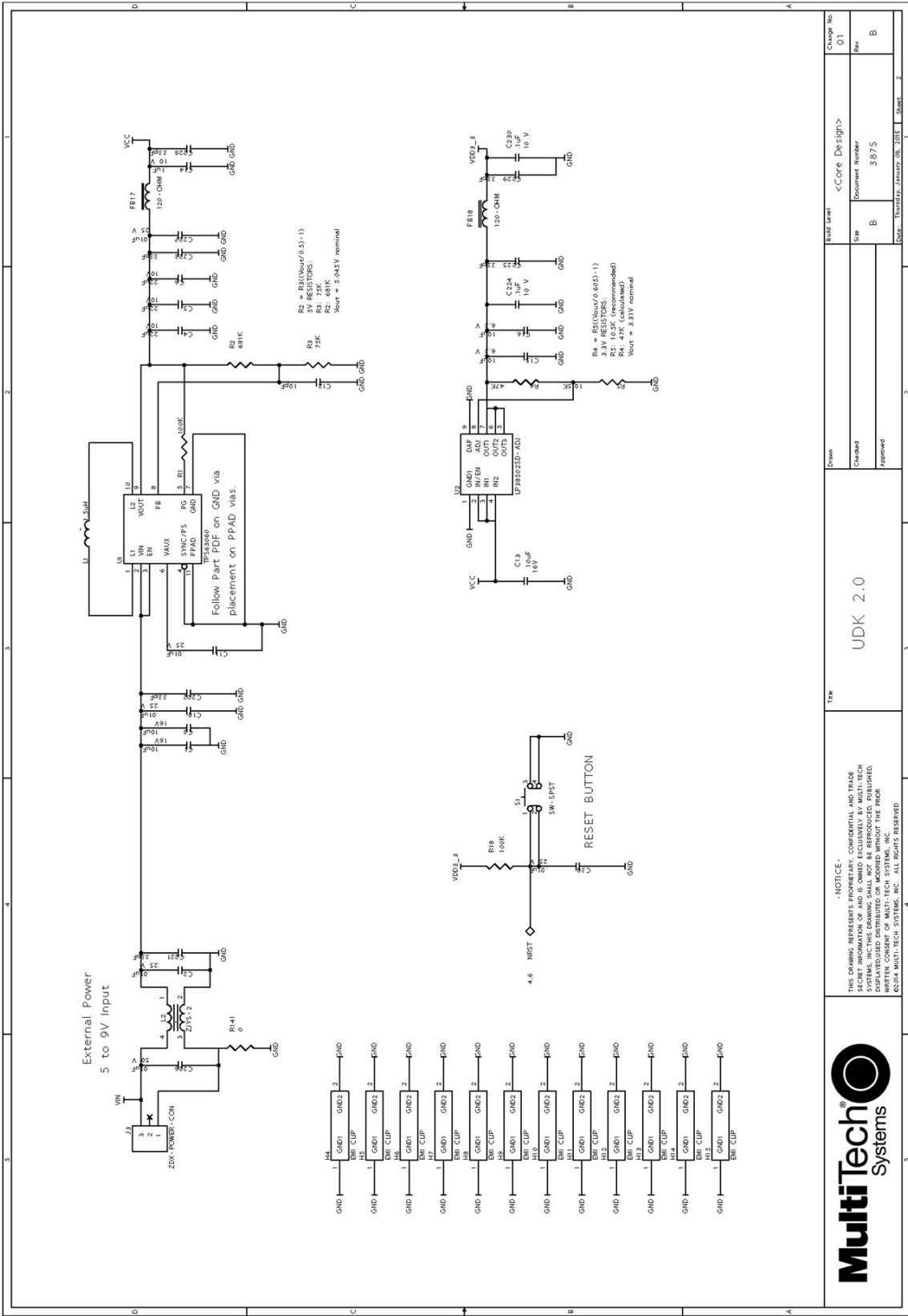


Chapter 12 Developer Board Schematics

Block Diagram



Schematics



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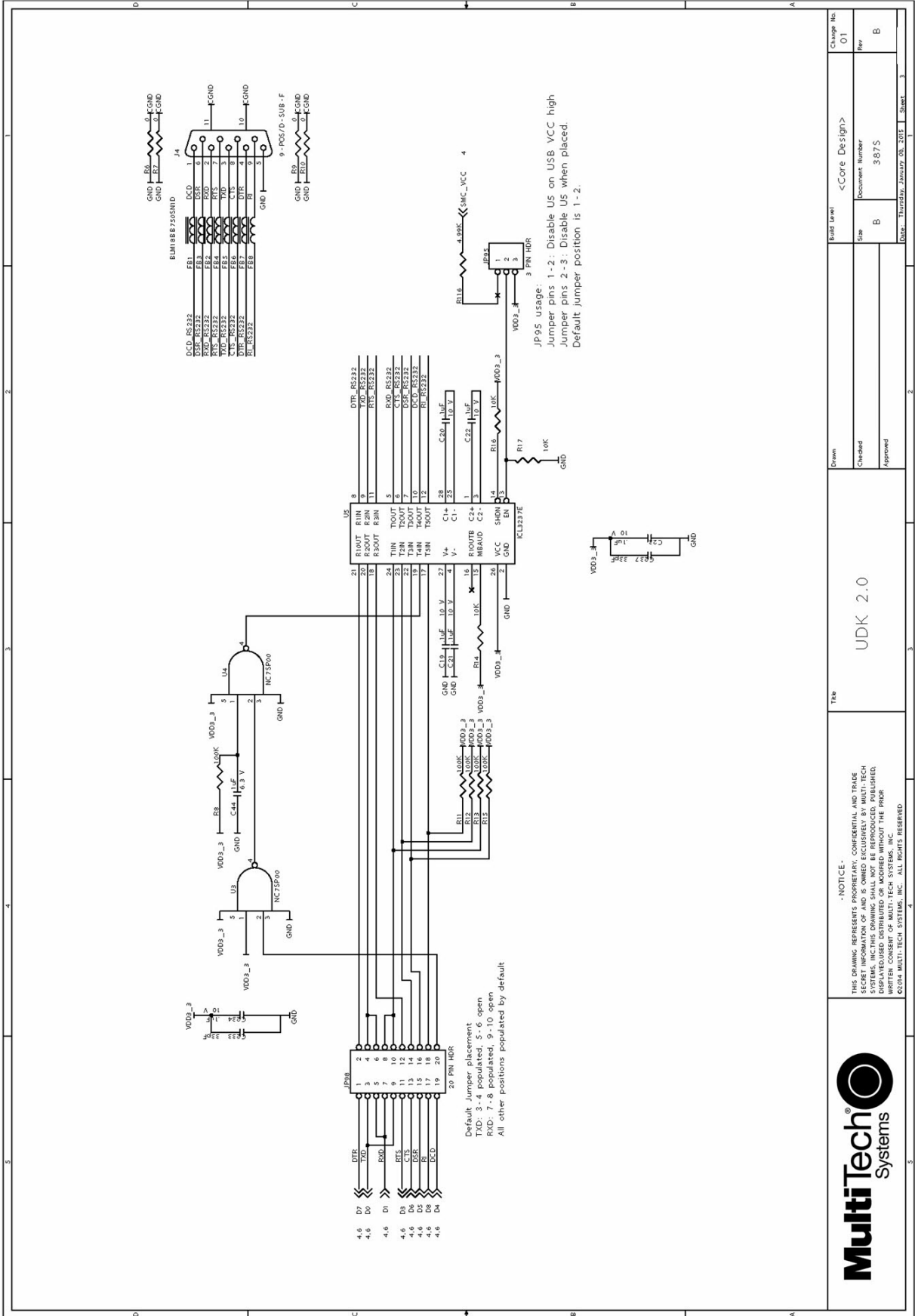
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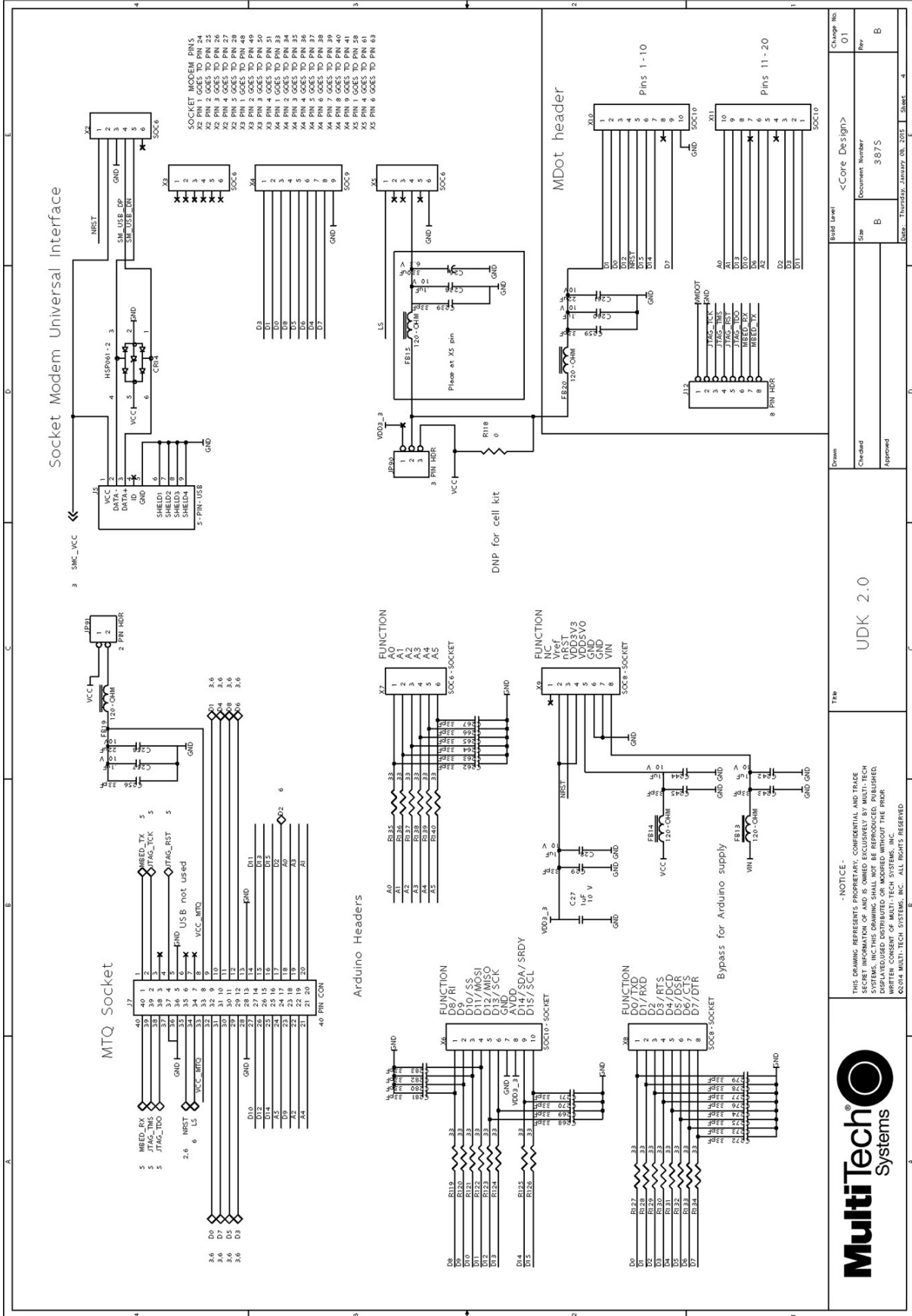
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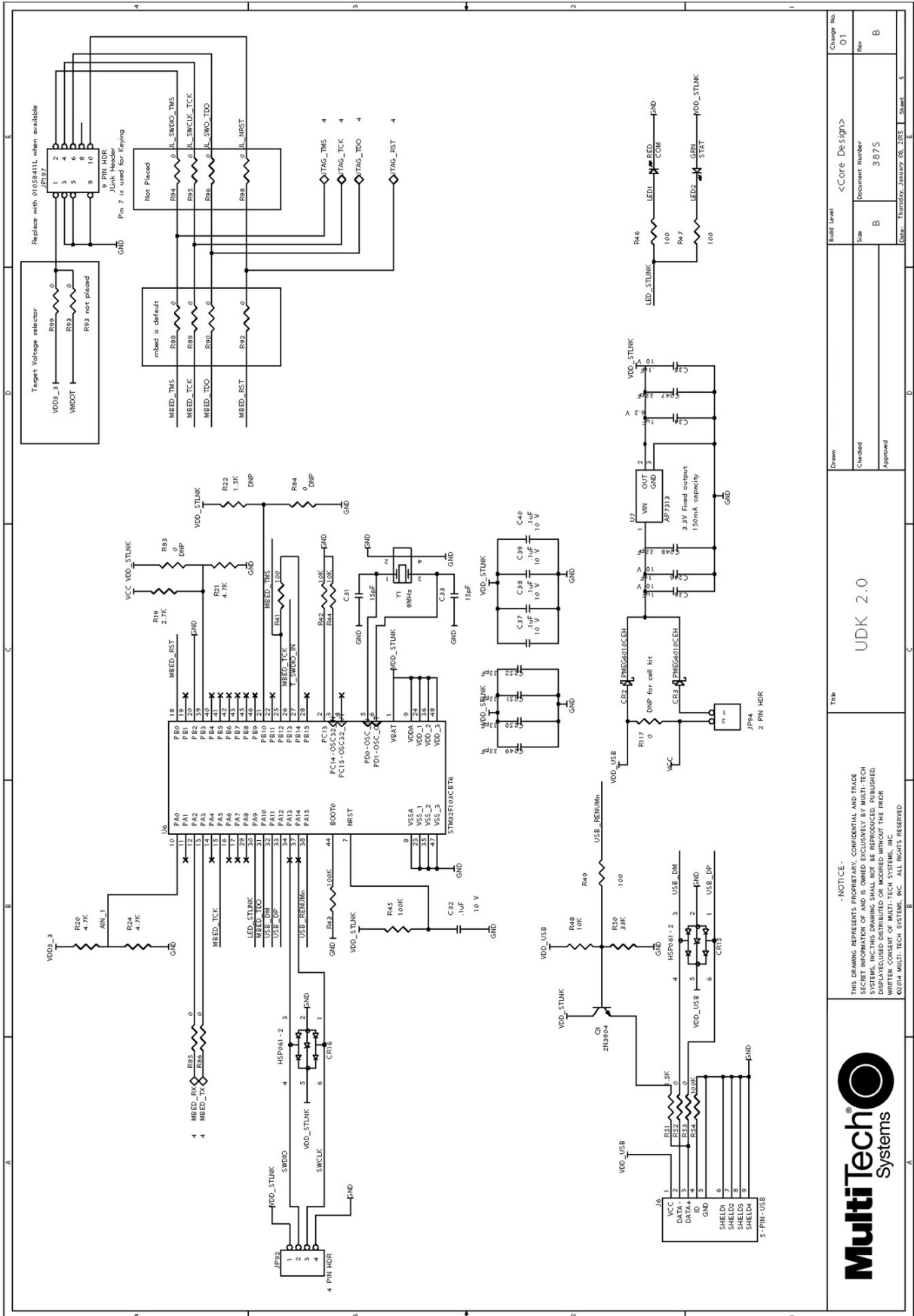
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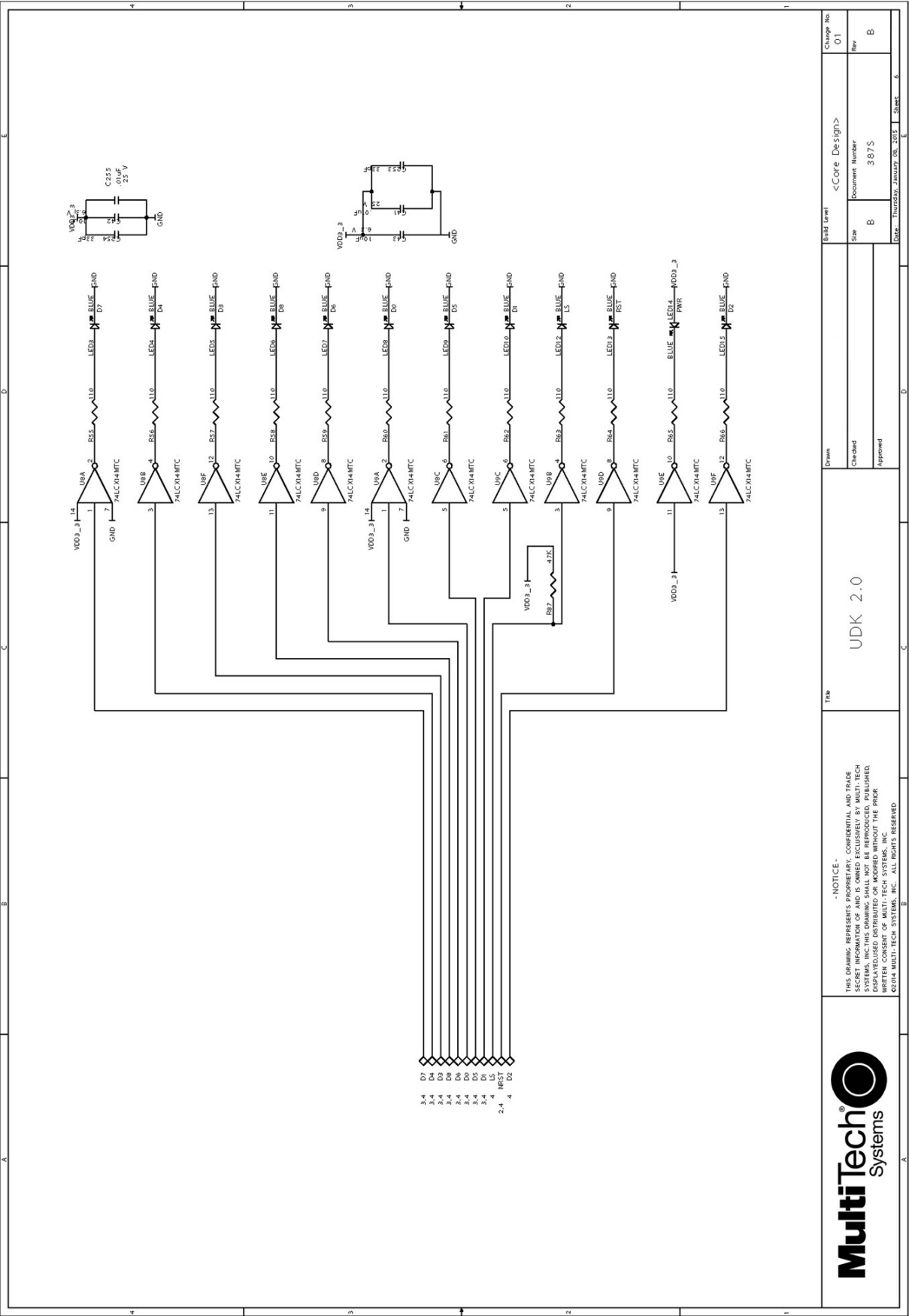
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Chapter 13 Design Considerations

Noise Suppression Design

Adhere to engineering noise-suppression practices when designing a printed circuit board (PCB). Noise suppression is essential to the proper operation and performance of the modem and surrounding equipment.

Any OEM board design must consider both on-board and off-board generated noise that can affect digital signal processing. Both on-board and off-board generated noise that is coupled on-board can affect interface signal levels and quality. Noise in frequency ranges that affect modem performance is of particular concern.

On-board generated electromagnetic interference (EMI) noise that can be radiated or conducted off-board is equally important. This type of noise can affect the operation of surrounding equipment. Most local government agencies have certification requirements that must be met for use in specific environments.

Proper PC board layout (component placement, signal routing, trace thickness and geometry, and so on) component selection (composition, value, and tolerance), interface connections, and shielding are required for the board design to achieve desired modem performance and to attain EMI certification.

Other aspects of proper noise-suppression engineering practices are beyond the scope of this guide. Consult noise suppression techniques described in technical publications and journals, electronics and electrical engineering text books, and component supplier application notes.

PC Board Layout Guideline

In a 4-layer design, provide adequate ground plane covering the entire board. In 4-layer designs, power and ground are typically on the inner layers. Ensure that all power and ground traces are 0.05 inches wide.

The recommended hole size for the device pins is 0.036 in. +/-0.003 in. in diameter. Use spacers to hold the device vertically in place during the wave solder process.

All creepages and clearances for the device meet requirements of safety standards listed in the technical specifications. The requirements are based on a working voltage of 125V or 250V. When implementing the recommended DAA* circuit interface in a third party design, strictly follow all creepage and clearance requirements to meet safety standards. The third party safety design must be evaluated by the appropriate national agency according to the required specification.

User Accessible Areas

Based on where the third party design is marketed, sold, or used, it may be necessary to provide an insulating cover over all TNV exposed areas. Consult with the recognized safety agency to determine the requirements.

Note: Even if the recommended design considerations are followed, there are no guarantees that a particular system complies with all the necessary regulatory requirements. Make sure a qualified and recognized agency evaluates specific designs. .

*DAA stands for Data Access Arrangement. DAA is the device's telephone line interface.

Electromagnetic Interference

The following guidelines are offered specifically to help minimize EMI generation. Some of these guidelines are the same as, or similar to, the general guidelines. To minimize the contribution of device-based design to EMI, you must understand the major sources of EMI and how to reduce them to acceptable levels.

- Keep traces carrying high frequency signals as short as possible.
- Provide a good ground plane or grid. In some cases, a multilayer board may be required with full layers for ground and power distribution.
- Decouple power from ground with decoupling capacitors as close to the device's power pins as possible.
- Eliminate ground loops, which are unexpected current return paths to the power source and ground.
- Decouple the telephone line cables at the telephone line jacks. Typically, use a combination of series inductors, common mode chokes, and shunt capacitors. Methods to decouple telephone lines are similar to decoupling power lines; however, telephone line decoupling may be more difficult and deserves additional attention. A commonly used design aid is to place footprints for these components and populate as necessary during performance/EMI testing and certification.
- Decouple the power cord at the power cord interface with decoupling capacitors. Methods to decouple power lines are similar to decoupling telephone lines.
- Locate high frequency circuits in a separate area to minimize capacitive coupling to other circuits.
- Locate cables and connectors to avoid coupling from high frequency circuits.
- Lay out the highest frequency signal traces next to the ground grid.
- If using a multilayer board design, make no cuts in the ground or power planes and be sure the ground plane covers all traces.
- Minimize the number of through-hole connections on traces carrying high frequency signals.
- Avoid right angle turns on high frequency traces. Forty-five degree corners are good; however, radius turns are better.
- On 2-layer boards with no ground grid, provide a shadow ground trace on the opposite side of the board to traces carrying high frequency signals. This will be effective as a high frequency ground return if it is three times the width of the signal traces.
- Distribute high frequency signals continuously on a single trace rather than several traces radiating from one point.

Electrostatic Discharge Control

Handle all electronic devices with precautions to avoid damage due to the static charge accumulation.

See the ANSI/ESD Association Standard (ANSI/ESD S20.20-1999) – a document “for the Development of an Electrostatic Discharge Control for Protection of Electrical and Electronic Parts, Assemblies and Equipment.” This document covers ESD Control Program Administrative Requirements, ESD Training, ESD Control Program Plan Technical Requirements (grounding/bonding systems, personnel grooming, protected areas, packaging, marking, equipment, and handling), and Sensitivity Testing.

MultiTech strives to follow these recommendations. Input protection circuitry is incorporated in MultiTech devices to minimize the effect of static buildup. Take precautions to avoid exposure to electrostatic discharge during handling.

MultiTech uses and recommends that others use anti-static boxes that create a faraday cage (packaging designed to exclude electromagnetic fields). MultiTech recommends that you use our packaging when returning a product and when you ship your products to your customers.

USB Design

MultiTech recommends that you review Intel's High Speed USB Platform Design Guidelines for information about USB signal routing, impedance, and layer stacking. Also:

- Shield USB cables with twisted pairs (especially those containing D+/D-).
- Use a single 5V power supply for USB devices. See Power Draw for current (ampere) requirements.
- Route D+/D- together in parallel with the trace spacing needed to achieve 90 ohms differential impedance for the USB pair and to maintain a 20 mil space from the USB pair and all other signals.
- If power is provided externally, use a common ground between the carrier board and the device.

Chapter 14 AT Commands

MultiTech AT Command Set

These commands are available in firmware Version 0.1.3. Some commands are not available in older firmware versions. For firmware upgrade instructions and to download the latest firmware go to <http://www.multitech.net/developer/software/mdot-software/mdot-firmware-upgrade/>.

General Commands

Command	Description	Details
AT	Attention	Returns OK
ATI	Request ID	Shows firmware and library version information.
ATZ	Reset CPU	Reset the CPU.
ATE0/1	Enable/Disable echo mode	ATE0: disable, ATE1: enable.
ATV0/1	Enable/Disable verbose mode	ATV0: disable, ATV1: enable.
AT&F	Reset factory defaults	Reset current configuration to factory defaults.
AT&W	Save configuration	Save configuration to flash memory.
AT&V	Display status/setting	Displays current settings and status.
AT&S	Display stats	Displays statistics
AT&R	Reset stats	Resets statistics
AT+IPR	Set serial baud rate	Defaults to 115200.
AT+DIPR	Set debug serial baud rate	Defaults to 115200.
AT+SMODE	Start up mode	0: AT command mode, 1: Serial data mode. If this is set to 1(serial data mode), auto join needs to be enabled so that a join is performed on power up or reset. To exit serial data mode (after +SMODE has been set to 1) reset or power cycle the mDot and input “+++” immediately. There is a one second window to gather “+++”. That puts the device in command mode but leaves +SMODE=1 such that a subsequent reset starts it in serial mode again.
AT+LOG	Debug log level	Enable or disable debug logging, 0: off, 1: Fatal - 6: Trace

Network/Addressing Commands

Command	Description	Details
AT+FREQ	Frequency Band	Read frequency band 868 or 915. Read only.
AT+FSB	Frequency Sub-band	Set the frequency sub-band for US 915. 0:ALL, 1-8.

Command	Description	Details
AT+PN	Public Network	Enable/disable public network mode. 0: off, 1: on.
AT+DI	Device ID	Device EUI (unique, set at factory), 8 bytes. Read only.
AT+NA	Network Address	Network address (devAddr in LoraMac), 4 bytes.
AT+NSK	Network Session Key	Network session encryption key, 16 bytes.
AT+DSK	Data Session Key	Data session encryption key (App session key in LoraMac), 16 bytes.
AT+NK	Network Key	Configured network key/passphrase (App Key in LoraMac) ## AT+NK=0,hex AT+NK=1,passphrase (Net key = cmac(passphrase)). 16 bytes.
AT+NI	Network ID	Configured Network EUI/Name (App EUI in LoraMac). AT+NI=0,hex AT+NI=1,network_name (Net ID = crc64(network_name), 8 bytes.
AT+JOIN	Join Network	Join network (acquire network address and session keys).
AT+JR	Join Retries	Number of times to retry joining the network in an attempt (0 - 255).
AT+JBO	Join Byte Order	Send EUIs in join request with configured byte ordering.
AT+NJM	Network Join Mode	0: Manual configuration, 1: OTA Network Join, 2: Auto OTA Network Join on start up. Default: 1. Note that 0 for manual configuration is part of LoRaWAN compliance.
AT+NJS	Network Join Status	Displays last known state. 0: Not joined, 1: Joined.
AT+NLC	Network Link Check	Perform network link check, OK or ERROR.
AT+LCC	Link Check Count	Set number of packets between each link and check if ACKs are disabled.
AT+LCT	Link Check Threshold	Set threshold for number of link check or ACK failures to tolerate. 0: off, N: number of failures.
AT+ENC	AES Encryption	Enable/disable AES encryption. 0: off, 1: on.
AT+RSSI	Signal Strength	Displays last received packet's signal strength.
AT+SNR	Signal To Noise Ratio	Display signal to noise ratio received packets last, minimum, maximum, average.
AT+DP	Data Pending	Indicator of data in queue on server.
AT+PING	Send Ping	Sends ping, displays RSSI and SNR from gateway on pong.

Radio Configuration

Command	Description	Details
AT+TXDR	Set Tx data rate	Set the Tx spread factor for all channels, 7-10.
AT+TXP	Set Tx Power	Set the Tx power for all channels.
AT+TXF	Tx Frequency	Set Tx frequency.

Command	Description	Details
AT+TXCH	Set Tx Channel	List channels for current sub-band. 0 = 902.7, 1 = 902.9, etc.
AT+TOA	Time On Air	Get packet transmit time in milliseconds with current data rate.
AT+TXI	Set Tx inverted	Set Tx signal inverted. Default: off.
AT+TXW	Tx Wait	Enable/disable waiting for rx windows to expire after send. 0: off, 1: on.
AT+RXDR	Set Rx Data Rate	Set the Rx spread factor for all channels, 7-10.
AT+RXF	Rx Frequency	Set the Rx frequency for +RECV,+RECV.
AT+RXI	Set Rx inverted	Set Rx signal inverted. Default :on
AT+FEC	Set Error Correction	Configure Forward Error Correction. 1 to 4.
AT+CRC	Set CRC Check On/Off	Enable/disable CRC checking received packets. 0: off, 1: on.
AT+ADR	Adaptive Data Rate	Enable/disable Adaptive Data Rate. 0: off, 1: on.

Send/Receive

Command	Description	Details
AT+ACK	Require Send ACK	Enable to require send acknowledgment. 0: off, N: number of retries until ACK received.
AT+SEND	Send Once	Sends supplied packet data one time and returns response.
AT+SENDB	Send Binary	Sends supplied binary (hex) packet data one time and returns response.
AT+SENDH	Send Once High BW	Sends supplied packet data one time and returns response using High Bandwidth channel. Max: 240 bytes.
AT+SENDI	Send Interval	Sends supplied packet data on interval (escape sequence: +++).
AT+RECV	Receive Once	Display last packet received.
AT+RECV	Receive Continuous	Continuously receive and display packets (escape sequence: +++).
AT+TXN	Tx Next	Get time until next free channel in milliseconds
AT+TOA	Time on Air	Get time in ms of packet tx with current data rate
AT+RXO	Rx Output	Set the Rx output type. 0:hexadecimal, 1: raw.

Sleep/Serial Data Mode Options

Command	Description	Details
AT+SD	Enter serial data mode	Reads serial data and sends LoRa packets (escape sequence: +++).

Command	Description	Details
AT+SLEEP	Sleep Mode	Enter sleep mode, wake on INTERVAL or INTERRUPT. The mDot will wake when the wake interval expires. Must issue AT+SLEEP to re-enter sleep mode.
AT+WM	Wake Mode	Wake up mode; Interrupt uses DIO7 as wake up pin; 0: INTERRUPT, 1: INTERVAL.
AT+WI	Wake Interval	Wake up interval (seconds).
AT+WD	Wake Delay	Maximum time to wait for data on serial port (milliseconds).
AT+WTO	Wake Timeout	Continue reading serial data until timeout (milliseconds).

Index

A	
antenna	24
connecting	45
Arduino Shield	44
AT commands	
MultiTech	55
B	
baud rate	22
block diagram	46
board components	41
build options	9
C	
cable	45
certification	
FCC	29
Industry Canada	30
certifications	16
Chinese hazardous substances	
Chinese version	35
English version	34
Class B	28
Industry Canada	29
Conduit	7
connectors	41
D	
DAA	52
data bits	22
dc characteristics	20
device	
maintenance	27
documentation	7
E	
electromagnetic interference	53
electrostatic discharge	53
EMI	52 53
ESD	53
EUI	8
F	
FCC	
grant notes	24
FCC certification	29
FCC Notice	
Class B	28
flow control	22
G	
ground plane	52
H	
handling precautions due to ESD	53
hazardous substances	33
host labeling	24
I	
identifier	8
IMEI location	36
Industry Canada	
Class B	29
install mDot	43
interférence des radiofréquences	26
K	
KDB 447498 Section 8	24
L	
labeling	
host	24
labels	36
LED indicators	42
LoRa	
range	22
M	
maintenance	27
mbed	7
mechanical drawings	10 11 12 13 14 15
MTAC-LORA	7

MTCDDT.....7
 MultiConnect7

N

networking8
 noise suppression.....52

P

packing list37
 parity22
 PC board layout.....52
 pin information20
 pinout notes.....22
 power draw19

R

radio frequency interference.....26
 range22
 receive sensitivity.....16
 related products.....7
 RoHS.....33
 RSMA to U.FL cable45

S

safety
 RF interference26
 safety standards.....52
 schematics.....47
 serial settings22
 SMA to U.FL.....45
 specifications.....16
 static.....26
 stop bits.....22
 sécurité
 interférences RF.....26

T

transmission.....16

U

U.FL45
 USB
 design consideration.....54
 user responsibility.....27